



12-Bit, 100-MSPS, 8-Channel Analog-to-Digital Converter

Check for Samples: ADS5295

FEATURES

- Maximum Sample Rate: 100 MSPS
- Designed for Low Power:
 - 80 mW per channel at 100 MSPS
- SNR: 70.6 dBFS
- SFDR: 85 dBc at 10 MHz, 100 MSPS
- Serial LVDS ADC Data Outputs:
 - One- or Two-Wire Serialized LVDS Outputs per Channel
 - One-Wire Interface:
 Up to 80 MSPS Sample Rate
 - Two-Wire Interface:
 Up to 100 MSPS Sample Rate
- Digital Processing Block:
 - Programmable FIR Decimation Filter and Oversampling to Minimize Harmonic Interference
 - Programmable IIR High-Pass Filter to Minimize DC Offset
 - Programmable Digital Gain: 0 dB to 12 dB
- Low-Frequency Noise Suppression Mode
- Programmable Mapping Between ADC Input Channels and LVDS Output Pins
- Channel Averaging Mode
- Variety of LVDS Test Patterns to Verify Data Capture by FPGA or Receiver
- Package: 12-mm x 12-mm QFP-80

APPLICATIONS

- Ultrasound Imaging
- Communication Applications
- Multichannel Data Acquisition

DESCRIPTION

The ADS5295 is a low-power, 12-bit, 100-MSPS, 8-channel analog-to-digital converter (ADC). Low power consumption and integration of multiple channels in a compact package make the device attractive for very high channel count data acquisition systems.

Serial low-voltage differential signaling (LVDS) outputs reduce the number of interface lines and enable high system integration. The ADC digital data can be output over one or two wires of LVDS pins per channel. At high sample rates, the two-wire interface helps keep the serial data rate low, allowing low-cost field-programmable gate array (FPGA)-based receivers to be used.

The device integrates an internal reference trimmed to accurately match across devices. Best performance is expected to be achieved through the internal reference mode. However, the device can be driven with external references as well.

Several digital functions that are commonly used in systems are included in the device. These functions include a low-frequency suppression mode, digital filtering options, and programmable mapping.

For low input frequency applications, the low-frequency noise suppression mode enables noise suppression at low frequencies and improves signal-to-noise ratio (SNR) in the 1-MHz band near dc by approximately 3 dB. Digital filtering options include low-pass, high-pass, and band-pass digital filters, as well as dc offset removal filters. The device also provides programmable mapping of the LVDS output pins and analog input channels. For applications where the 12-bit ADC SNR is not required, the ADS5295 can be configured as an 8-channel, 10-bit ADC with 10x LVDS serialization to reduce the output data rate.

The device is available in a 12-mm × 12-mm QFP-80 package. The ADS5295 is specified over the -40°C to +85°C operating temperature range.





This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

ORDERING INFORMATION(1)

PRODUCT	PACKAGE-LEAD	PACKAGE DESIGNATOR	SPECIFIED TEMPERATURE RANGE	PACKAGE MARKING	ORDERING NUMBER
ADS5295	TQFP-80	PFP	-40°C to +85°C	ADS5295	ADS5295IPFP

⁽¹⁾ For the most current package and ordering information, see the Package Option Addendum at the end of this document, or visit the device product folder at www.ti.com.

ABSOLUTE MAXIMUM RATINGS(1)

Over operating free-air temperature range, unless otherwise noted.

P/	ARAMETER	VALUE	UNIT
Complementary	AVDD	-0.3 to 2.2	V
Supply voltage range	LVDD	-0.3 to 2.2	V
	AGND and LGND	-0.3 to 0.3	V
Voltage between	AVDD to LVDD (when AVDD leads LVDD)	0 to 2.2	V
	LVDD to AVDD (when LVDD leads AVDD)	0 to 2.2	V
	INP, INN	-0.3 to min (2.2, AVDD + 0.3)	V
Voltage applied to	RESET, SCLK, SDATA, $\overline{\text{CS}}$, PD, SYNC, CLKP, CLKN ⁽²⁾	-0.3 to min (2.2, AVDD + 0.3)	V
	Digital outputs	-0.3 to min (2.2, LVDD + 0.3)	V
	Operating free-air, T _A	-40 to +85	°C
Temperature range	Operating junction, T _J	+105	°C
	Storage, T _{stg}	−55 to +150	°C
Electrostatic discharge (ESD) rating	Human body model (HBM)	2000	V

⁽¹⁾ Stresses above these ratings may cause permanent damage. Exposure to absolute maximum conditions for extended periods may degrade device reliability. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those specified is not implied.

THERMAL INFORMATION

		ADS5295	
	THERMAL METRIC ⁽¹⁾	PFP (TQFP)	UNITS
		80 PINS	
θ_{JA}	Junction-to-ambient thermal resistance	30.8	
θ_{JCtop}	Junction-to-case (top) thermal resistance	6.3	
θ_{JB}	Junction-to-board thermal resistance	8.3	00044
ΨЈТ	Junction-to-top characterization parameter	0.2	°C/W
ΨЈВ	Junction-to-board characterization parameter	8.2	
θ_{JCbot}	Junction-to-case (bottom) thermal resistance	0.3	

(1) For more information about traditional and new thermal metrics, see the IC Package Thermal Metrics application report, SPRA953.

⁽²⁾ When AVDD is turned off, TI recommends switching off the input clock (or ensuring the voltage on CLKP and CLKN is less than |0.3 V|. This setting prevents the ESD protection diodes at the clock input pins from turning on.



RECOMMENDED OPERATING CONDITIONS

			MIN	NOM	MAX	UNIT
SUPPLIES			-		*	
AVDD	Analog supply voltage		1.7	1.8	1.9	V
LVDD	Digital supply voltage		1.7	1.8	1.9	V
ANALOG IN	PUTS		·			
V _{ID}	Differential input voltage range			2		V_{PP}
	Input common-mode voltage		VC	M ± 0.05		V
REFT	External reference mode			1.45		V
REFB	External reference mode			0.45		V
VCM	Common-mode voltage output			0.95		V
CLOCK INP	UTS (ADCLK Input Sample Rate)					
	ADCLK input sample rate (1 / t _C)	One-wire LVDS interface	10		80	MSPS
	ADCER input sample rate (1 / t _C)	Two-wire LVDS interface	10		100	MSPS
		Sine-wave, ac-coupled		1.5		V_{PP}
	Input clock amplitude differential (VCLKP – VCLKN)	LVPECL, ac-coupled		1.6		V_{PP}
	(102.11 102.11)	LVDS, ac-coupled		0.7		V_{PP}
	Input clock CMOS single-ended	V_{IL}		< 0.3		V
	(VCLKP)	V _{IH}		> 1.5		V
	Input clock duty cycle		35 50 65		%	
DIGITAL OU	JTPUTS					
	ADCLKP and ADCLKN outputs (L	VDS), one-wire	(sampl	1x e rate in MSPS)		MHz
	ADCLKP and ADCLKN outputs (L	VDS), two-wire	(sampl	0.5x (sample rate in MSPS)		
	LCLKP and LCLKN outputs	12x serialization	(sampl	6x e rate in MSPS)		MHz
	(LVDS), one-wire	10x serialization	(sampl	5x e rate in MSPS)		MHz
	LCLKP and LCLKN outputs	12x serialization	(sampl	3x (sample rate in MSPS)		MHz
	(LVDS), two-wire	10x serialization	(sampl	2.5x e rate in MSPS)		MHz

INSTRUMENTS

SBAS595 – DECEMBER 2012 www.ti.com

ELECTRICAL CHARACTERISTICS: General

Typical values are at T_A = +25°C, AVDD = 1.8 V, LVDD = 1.8 V, 50% clock duty cycle, 100 MSPS, two-wire LVDS interface, and -1-dBFS differential analog input, unless otherwise noted.

Minimum and maximum values are across the full temperature range of $T_{MIN} = -40$ °C to $T_{MAX} = +85$ °C, AVDD = 1.8 V, and LVDD = 1.8 V.

	PARAI	METER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
RESOLU'	TION						
	Resolution					12	Bits
ANALOG	INPUTS						
	Differential input	voltage range			2.0		V_{PP}
	Differential input	resistance	At dc		2		kΩ
	Differential input capacitance		At dc		3.7		pF
	Analog input bandwidth				500		MHz
	Analog input common-mode current (per input pin)				1		μA/MSPS
VCM	Common-mode output voltage VCM output current capability				0.95		V
					5		mA
DYNAMIC	CACCURACY						
Eo	Offset error			-20		20	mV
E _{GREF}	Gain error	Resulting from internal reference inaccuracy alone		-1.5		1.5	%FS
E _{GCHAN}		Of channel itself			0.5		%FS
	E _{GCHAN} temperate	ure coefficient			< 0.01		Δ%FS/°C
POWER S	SUPPLY						
IAVDD	Analog supply cu	rrent	100 MSPS		206	225	mA
ILVDD	Output buffer sup	pply current	100 MSPS, two-wire LVDS interface, 350-mV swing with 100-Ω external termination		150	163	mA
AVDD	Analog power		100 MSPS		370.8		mW
LVDD	Digital power		100 MSPS, two-wire LVDS interface, 350-mV swing with 100-Ω external termination		270		mW
	Total power		100 MSPS, two-wire LVDS interface, 350-mV swing with 100-Ω external termination		640.8		mW
	Global power-dov	vn				45	mW
	Standby power				192		mW



ELECTRICAL CHARACTERISTICS: Dynamic Performance

Typical values are at T_A = +25°C, AVDD = 1.8 V, LVDD = 1.8 V, maximum rated sampling frequency, 50% clock duty cycle, 100 MSPS, two-wire LVDS interface, and -1-dBFS differential analog input, unless otherwise noted. Minimum and maximum values are across the full temperature range of T_{MIN} = -40°C to T_{MAX} = +85°C, AVDD = 1.8 V, and LVDD = 1.8 V.

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
		f _{IN} = 5 MHz	67.5	70.6		dBFS
SNR	Signal-to-noise ratio	f _{IN} = 30 MHz		70.4		dBFS
		f _{IN} = 70 MHz		69.7		dBFS
		f _{IN} = 5 MHz	66	70.4		dBFS
SINAD	Signal-to-noise and distortion ratio	f _{IN} = 30 MHz		70		dBFS
		f _{IN} = 70 MHz		68.9		dBFS
		f _{IN} = 5 MHz	72.5	86		dBc
SFDR	Spurious-free dynamic range	f _{IN} = 30 MHz		79		dBc
		f _{IN} = 70 MHz		76.3		dBc
		f _{IN} = 5 MHz	71	85		dBc
THD	Total harmonic distortion	f _{IN} = 30 MHz		78.4		dBc
		f _{IN} = 70 MHz		75.8		dBc
		f _{IN} = 5 MHz	72.5	89.5		dBc
HD2	Second-harmonic distortion	f _{IN} = 30 MHz		89.5		dBc
		f _{IN} = 70 MHz		89.5		dBc
		f _{IN} = 5 MHz	72.5	86		dBc
HD3	Third-harmonic distortion	f _{IN} = 30 MHz		79		dBc
		f _{IN} = 70 MHz		76.4		dBc
		f _{IN} = 5 MHz	75	95		dBc
	Worst spur (other than second and third harmonics)	f _{IN} = 30 MHz		93		dBc
	(other than second and third namionics)	f _{IN} = 70 MHz		82.3		dBc
IMD	Two-tone intermodulation distortion	f ₁ = 8 MHz, f ₂ = 10 MHz, each tone at -7 dBFS		86		dBc
	Crosstalk	10-MHz full-scale signal on aggressor channel; 5-MHz input signal applied on victim channel		86		dB
	Input overload recovery	Recovery to within 1% (of full-scale) for 6-dB overload with sine-wave input		1		Clock cycle
PSRR	AC power-supply rejection ratio	For 50-mV _{PP} signal on AVDD supply, up to 10 MHz, no signal applied to analog inputs		60		dB
ENOB	Effective number of bits	f _{IN} = 5 MHz		11.4		LSBs
DNL	Differential nonlinearity	f _{IN} = 5 MHz	-0.82	±0.05	0.82	LSBs
INL	Integrated nonlinearity	f _{IN} = 5 MHz		0.4	1.1	LSBs



DIGITAL CHARACTERISTICS

The dc specifications refer to the condition where the digital outputs are not switching, but are permanently at a valid logic level '0' or '1'. AVDD = 1.8 V and DRVDD = 1.8 V.

	PARAMET	ER	TEST CONDITIONS	MIN TYP	MAX	UNIT
DIGITA	AL INPUTS (RESET, SCLK, S	SDATA, CS, SYNC, PDN)		ı		
V _{IH}	High-level input voltage		All pins support 1.8-V and 3.3-V CMOS logic levels	1.3		V
V _{IL}	Low-level input voltage		All pins support 1.8-V and 3.3-V CMOS logic levels		0.4	V
I _{IH}	High-level input current	CS, SDATA, SCLK ⁽¹⁾	V _{HIGH} = 1.8 V	6		μΑ
I _{IL}	Low-level input current	CS, SDATA, SCLK ⁽¹⁾	V _{LOW} = 0 V	0.1		μΑ
DIGITA	AL OUTPUTS (CMOS INTERI	FACE: SDOUT)				
V _{OH}	High-level output voltage			AVDD - 0.1		V
V _{OL}	Low-level output voltage				0.1	V
DIGITA	AL OUTPUTS (LVDS INTERF	ACE: OUT1A_P, OUT1A_N	to OUT8A_P, OUT8A_N and OUT1B_P, OU	T1B_N to OUT8B_P, OUT8	B_N)	
V _{ODH}	High-level output differentia	al voltage ⁽²⁾		300	485	mV
V_{ODL}	Low-level output differentia	l voltage ⁽²⁾		-485	-300	mV
V_{OCM}	Output common-mode volta	age		0.95	1.35	V

⁽¹⁾ $\overline{\text{CS}}$, SDATA, and SCLK have an internal 220-k Ω pull-down resistor.

⁽²⁾ With an external 100-Ω termination.



TIMING REQUIREMENTS(1)

Typical values are at +25°C, AVDD = 1.8 V, LVDD = 1.8 V, sampling frequency = 100 MSPS, sine-wave input clock, C_{LOAD} = 5 pF, and R_{LOAD} = 100 Ω , unless otherwise noted.

Minimum and maximum values are across the full temperature range of $T_{MIN} = -40$ °C to $T_{MAX} = +85$ °C, AVDD = 1.8 V, and LVDD = 1.7 V to 1.9 V.

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t _A	Aperture delay			4		ns
	Aperture delay matching	Between any two channels of the same device		±200		ps
	Variation of aperture delay	Between two devices at the same temperature and LVDD supply		±1		ns
t _J	Aperture jitter	Sample uncertainty		320		fs rms
		Time to valid data after coming out of standby		5		μs
	Wake-up time	Time to valid data after coming out of global power-down mode		100		μs
	ADC latency ⁽²⁾	One-wire LVDS Output interface		12		Clock cycles
	ADC laterity -/	Two-wire LVDS Output interface		16		Clock cycles
TWO-WI	RE, 12x SERIALIZATION					
t _{SU}	Data setup time	Data valid to zero-crossing of LCLKP	0.52			ns
t _H	Data hold time	Zero-crossing of LCLKP to data becoming invalid	0.62			ns
t _{PDI}	Clock propagation delay	Input clock rising edge crossover to output clock rising edge crossover	t _{PDI} = (11/12) × t _S + t _{DELAY}		ns	
t _{DELAY}	Delay time		8.5	11	13.5	ns
	LVDS bit clock duty cycle	Duty cycle of differential clock (LCLKP – LCLKN)		50		%
ACROSS	S ALL SERIALIZATION MODES					
t _{FALL}	Data fall time	Rise time measured from −100 mV to +100 mV, 10 MSPS ≤ sampling frequency ≤ 100 MSPS		0.11		ns
t _{RISE}	Data rise time	Rise time measured from −100 mV to +100 mV, 10 MSPS ≤ sampling frequency ≤ 100 MSPS	0.11		ns	
t _{CLKRISE}	Output clock rise time	Rise time measured from −100 mV to +100 mV, 10 MSPS ≤ sampling frequency ≤ 100 MSPS	0.11		ns	
t _{CLKFALL}	Output clock fall time	Rise time measured from −100 mV to +100 mV, 10 MSPS ≤ sampling frequency ≤ 100 MSPS		0.11		ns

⁽¹⁾ Timing parameters are ensured by design and characterization, but are not tested in production.

⁽²⁾ At higher frequencies, t_{PDI} is greater than one clock period and the overall latency = ADC latency + 1.





Table 1. Two-Wire, 12x Serialization (1)(2)

SAMPLING	SETUP TIME (ns)			HOLD TIME (ns)			t _{PDI} = (11/12) × t _S + t _{DELAY} Where t _{DELAY} is specified as below, ns		
FREQUENCY (MSPS)	MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX
10	7.80			8.00			8.5	11	13.5
30	2.40			2.50			8.5	11	13.5
50	1.10			1.60			8.5	11	13.5
65	0.83			1.25			8.5	11	13.5
80	0.60			1.00			8.5	11	13.5
100	0.52			0.62			8.5	11	13.5

(1) All the timing specifications are taken with default output clock and data delay settings (0 ps).

Table 2. One-Wire, 12x Serialization (1)(2)

SAMPLING	SETU	P TIME (ns)		HOL	D TIME (ns)		Where t _{DEL}	12) × t _S + t _{DE} _{AY} is specifi elow, ns	ELAY ed as
FREQUENCY (MSPS)	MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX
10	3.90			4.00			8	10	12
30	1.00			1.30			8	10	12
50	0.60			0.57			8	10	12
65	0.40			0.34			8	10	12
80	0.22			0.24			8	10	12

(1) All the timing specifications are taken with default output clock and data delay settings (0 ps).

Table 3. Two-Wire, 10x Serialization⁽¹⁾⁽²⁾

SAMPLING FREQUENCY (MSPS)	SETU	P TIME (ns)		HOLD TIME (ns)			
	MIN	TYP	MAX	MIN	TYP	MAX	
65	1.00			1.50			
80	0.74			1.20			
100	0.44			1.00			

(1) All the timing specifications are taken with default output clock and data delay settings (0 ps).

Table 4. One-Wire, 10x Serialization (1)(2)

SAMPLING FREQUENCY (MSPS)	SETU	P TIME (ns)		HOLD TIME (ns)			
	MIN	TYP	MAX	MIN	TYP	MAX	
65	0.51			0.60			
80	0.33			0.36			
100	0.17			0.31			

(1) All the timing specifications are taken with default output clock and data delay settings (0 ps).

⁽²⁾ Refer to the Programmable LVDS Output Clock and Data Edges section in the Application Information for output clock and data delay options.

⁽²⁾ Refer to the Programmable LVDS Output Clock and Data Edges section in the Application Information for output clock and data delay options.

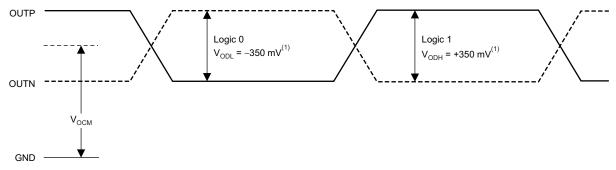
⁽²⁾ Refer to the Programmable LVDS Output Clock and Data Edges section in the Application Information for output clock and data delay options.

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PARAMETRIC MEASUREMENT INFORMATION

LATENCY TIMING

Figure 1 shows a timing diagram of the LVDS output voltage levels.



(1) With an external $100-\Omega$ termination.

Figure 1. LVDS Output Voltage Levels

Figure 2 shows a latency timing diagram.

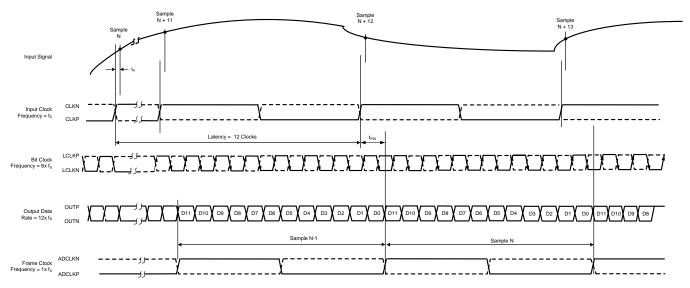


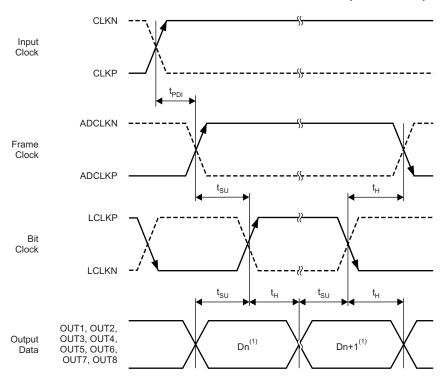
Figure 2. Latency Timing Diagram

LVDS OUTPUT TIMING

Figure 3 shows the output timing described in the Timing Requirements table.



PARAMETRIC MEASUREMENT INFORMATION (continued)



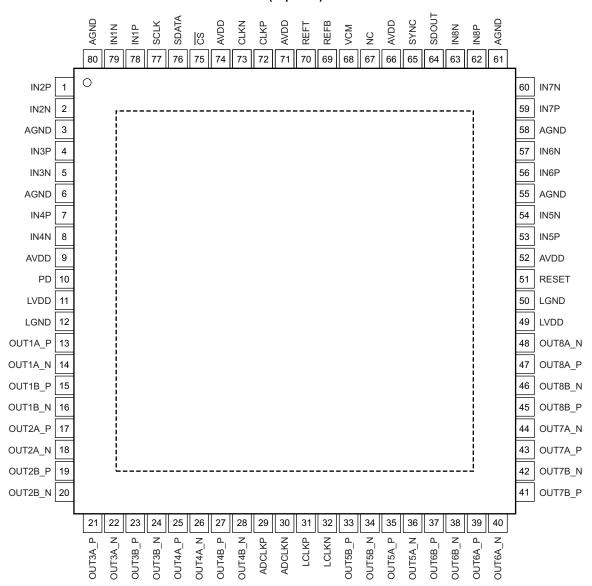
(1) n = 0 to 11.

Figure 3. LVDS Output Timing

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PIN DESCRIPTION

PFP PACKAGE TQFP-80 (Top View)







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PIN DESCRIPTIONS

			CRIPTIONS
NAME	NO.	FUNCTION ⁽¹⁾	DESCRIPTION
ADCLKN	30	DO	Differential LVDS frame clock (1x), negative
ADCLKP	29	DO	Differential LVDS frame clock (1x), positive
AGND	3, 6, 55, 58, 61, 80	G	Analog ground pin
AVDD	9, 52, 66, 71, 74	S	Analog supply pin, 1.8 V
CLKN	73	Al	Differential clock input, negative For a single-ended clock, tie CLKN to 0 V
CLKP	72	Al	Differential clock input, positive
<u>cs</u>	75	DI	Serial enable chip select; active low digital input
IN1N	79	Al	Differential analog input for channel 1, negative
IN1P	78	Al	Differential analog input for channel 1, positive
IN2N	2	Al	Differential analog input for channel 2, negative
IN2P	1	Al	Differential analog input for channel 2, positive
IN3N	5	Al	Differential analog input for channel 3, negative
IN3P	4	Al	Differential analog input for channel 3, positive
IN4N	8	Al	Differential analog input for channel 4, negative
IN4P	7	Al	Differential analog input for channel 4, positive
IN5N	54	Al	Differential analog input for channel 5, negative
IN5P	53	Al	Differential analog input for channel 5, positive
IN6N	57	Al	Differential analog input for channel 6, negative
IN6P	56	Al	Differential analog input for channel 6, positive
IN7N	60	Al	Differential analog input for channel 7, negative
IN7P	59	Al	Differential analog input for channel 7, positive
IN8N	63	Al	Differential analog input for channel 8, negative
IN8P	62	Al	Differential analog input for channel 8, positive
LCLKN	32	DO	LVDS differential bit clock output pins (6x), negative
LCLKP	31	DO	LVDS differential bit clock output pins (6x), positive
LGND	12, 50	G	Digital ground pin
LVDD	11, 49	S	Digital and I/O power supply, 1.8 V
NC	67	_	Do not connect
OUT1A_N	14	DO	Channel 1 differential LVDS negative data output, one-wire
OUT1A_P	13	DO	Channel 1 differential LVDS positive data output, one-wire
OUT1B_N	16	DO	Channel 1 differential LVDS negative data output, two-wire
OUT1B_P	15	DO	Channel 1 differential LVDS positive data output, two-wire
OUT2A_N	18	DO	Channel 2 differential LVDS negative data output, one-wire
OUT2A_P	17	DO	Channel 2 differential LVDS positive data output, one-wire
OUT2B_N	20	DO	Channel 2 differential LVDS negative data output, two-wire
OUT2B_P	19	DO	Channel 2 differential LVDS positive data output, two-wire
OUT3A_N	22	DO	Channel 3 differential LVDS negative data output, one-wire
OUT3A_P	21	DO	Channel 3 differential LVDS positive data output, one-wire
OUT3B_N	24	DO	Channel 3 differential LVDS negative data output, two-wire
OUT3B_P	23	DO	Channel 3 differential LVDS positive data output, two-wire
OUT4A_N	26	DO	Channel 4 differential LVDS negative data output, one-wire
OUT4A_P	25	DO	Channel 4 differential LVDS positive data output, one-wire
OUT4B_N	28	DO	Channel 4 differential LVDS negative data output, two-wire
OUT4B_P	27	DO	Channel 4 differential LVDS positive data output, two-wire
20170_1	۷.	50	S. a or 1 amoronia 2100 positivo data output, two wife

⁽¹⁾ Pin functionality: AI = analog input; DI = digital input; DO = digital output; G = ground; and S = supply.

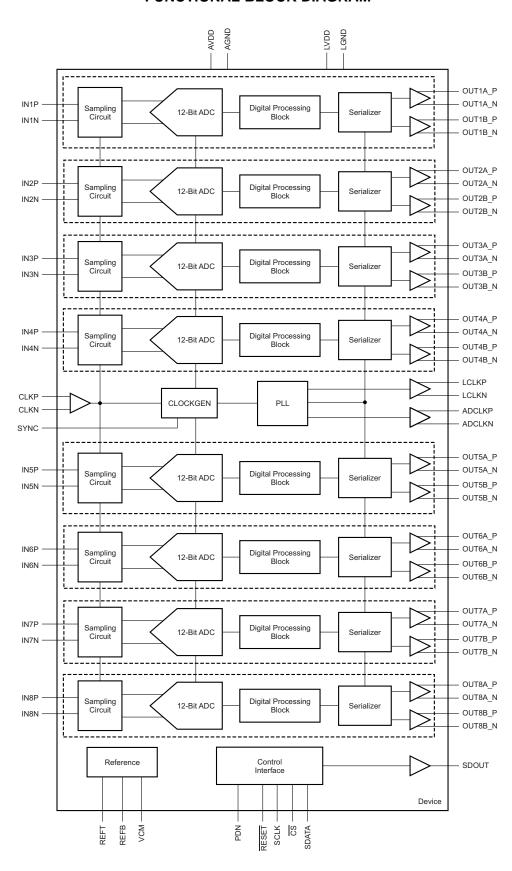


PIN DESCRIPTIONS (continued)

NAME	NO.	FUNCTION ⁽¹⁾	DESCRIPTION
OUT5B_N	34	DO	Channel 5 differential LVDS negative data output, two-wire
OUT5B_P	33	DO	Channel 5 differential LVDS positive data output, two-wire
OUT5A_N	36	DO	Channel 5 differential LVDS negative data output, one-wire
OUT5A_P	35	DO	Channel 5 differential LVDS positive data output, one-wire
OUT6B_N	38	DO	Channel 6 differential LVDS negative data output, two-wire
OUT6B_P	37	DO	Channel 6 differential LVDS positive data output, two-wire
OUT6A_N	40	DO	Channel 6 differential LVDS negative data output, one-wire
OUT6A_P	39	DO	Channel 6 differential LVDS positive data output, one-wire
OUT7B_N	42	DO	Channel 7 differential LVDS negative data output, two-wire
OUT7B_P	41	DO	Channel 7 differential LVDS positive data output, two-wire
OUT7A_N	44	DO	Channel 7 differential LVDS negative data output, one-wire
OUT7A_P	43	DO	Channel 7 differential LVDS positive data output, one-wire
OUT8B_N	46	DO	Channel 8 differential LVDS negative data output, two-wire
OUT8B_P	45	DO	Channel 8 differential LVDS positive data output, two-wire
OUT8A_N	48	DO	Channel 8 differential LVDS negative data output, one-wire
OUT8A_P	47	DO	Channel 8 differential LVDS positive data output, one-wire
PD	10	DI	Power-down control input pin
REFB	69	Al	Negative reference input/output
REFT	70	Al	Positive reference input/output
RESET	51	DI	Active high RESET input
SCLK	77	DI	Serial clock input
SDATA	76	DI	Serial data input
SDOUT	64	DO	Serial data output
SYNC	65	DI	Synchronization input for reduced output data rate
VCM	68	Al	Common-mode output pin, 0.95-V output



FUNCTIONAL BLOCK DIAGRAM





TYPICAL CHARACTERISTICS: General

Typical values are at $T_A = +25$ °C, AVDD = 1.8 V, LVDD = 1.8 V, 50% clock duty cycle, 100 MSPS, two-wire LVDS interface, and -1-dBFS differential analog input, unless otherwise noted.

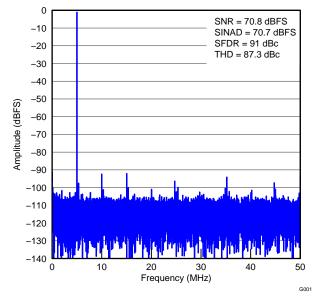


Figure 4. FFT FOR 5-MHz INPUT SIGNAL (Sample Rate = 100 MSPS)

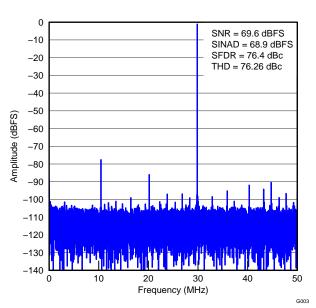


Figure 6. FFT FOR 70-MHz INPUT SIGNAL (Sample Rate = 100 MSPS)

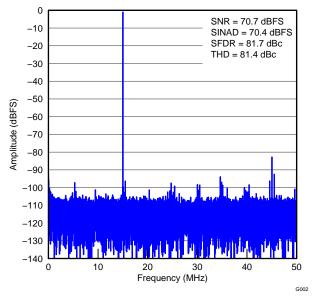


Figure 5. FFT FOR 15-MHz INPUT SIGNAL (Sample Rate = 100 MSPS)

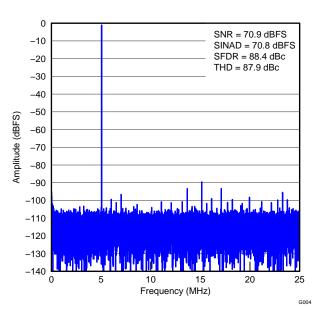


Figure 7. FFT FOR 5-MHz INPUT SIGNAL (Sample Rate = 50 MSPS)



TYPICAL CHARACTERISTICS: General (continued)

Typical values are at $T_A = +25$ °C, AVDD = 1.8 V, LVDD = 1.8 V, 50% clock duty cycle, 100 MSPS, two-wire LVDS interface, and -1-dBFS differential analog input, unless otherwise noted.

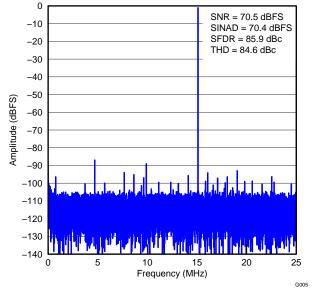


Figure 8. FFT FOR 15-MHz INPUT SIGNAL (Sample Rate = 50 MSPS)

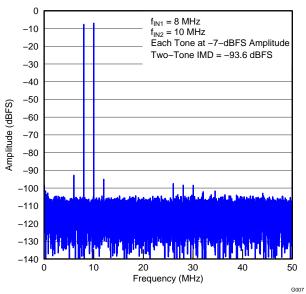
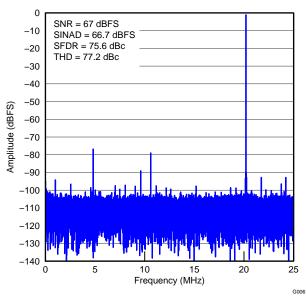


Figure 10. FFT WITH TWO-TONE SIGNAL



NSTRUMENTS

Figure 9. FFT FOR 70-MHz INPUT SIGNAL (Sample Rate = 50 MSPS)

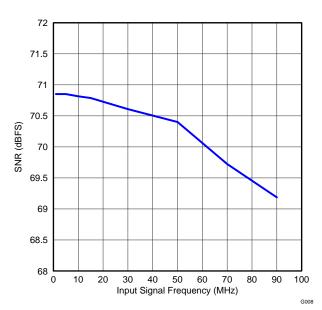


Figure 11. SIGNAL-TO-NOISE RATIO vs INPUT SIGNAL FREQUENCY



TYPICAL CHARACTERISTICS: General (continued)

Typical values are at T_A = +25°C, AVDD = 1.8 V, LVDD = 1.8 V, 50% clock duty cycle, 100 MSPS, two-wire LVDS interface, and -1-dBFS differential analog input, unless otherwise noted.

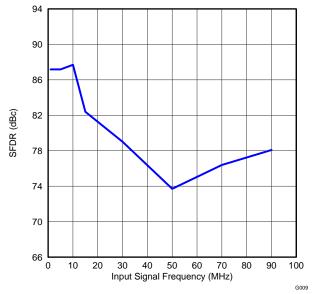


Figure 12. SPURIOUS-FREE DYNAMIC RANGE vs INPUT SIGNAL FREQUENCY

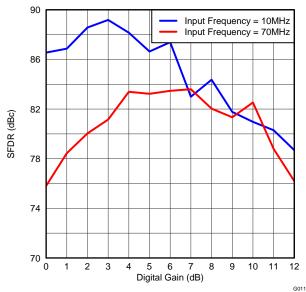


Figure 14. SPURIOUS-FREE DYNAMIC RANGE vs DIGITAL GAIN

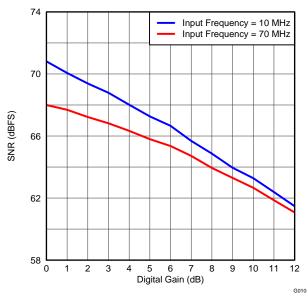


Figure 13. SIGNAL-TO-NOISE RATIO vs DIGITAL GAIN

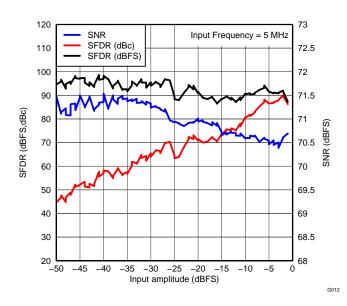
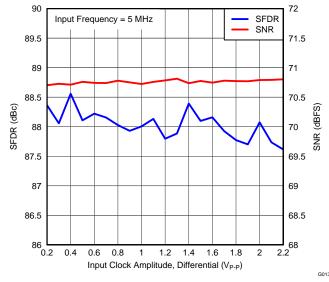


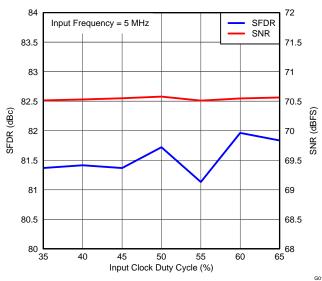
Figure 15. PERFORMANCE vs INPUT AMPLITUDE



TYPICAL CHARACTERISTICS: General (continued)

Typical values are at $T_A = +25$ °C, AVDD = 1.8 V, LVDD = 1.8 V, 50% clock duty cycle, 100 MSPS, two-wire LVDS interface, and -1-dBFS differential analog input, unless otherwise noted.

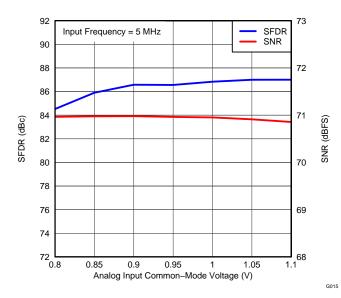




NSTRUMENTS

Figure 16. PERFORMANCE vs INPUT CLOCK AMPLITUDE

Figure 17. PERFORMANCE vs INPUT CLOCK DUTY CYCLE



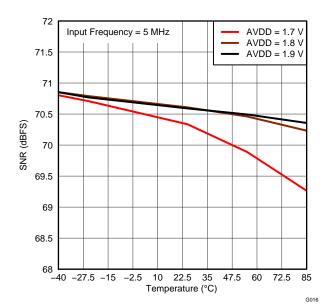


Figure 18. PERFORMANCE vs INPUT COMMON-MODE VOLTAGE

Figure 19. SIGNAL-TO-NOISE RATIO vs AVDD AND TEMPERATURE



TYPICAL CHARACTERISTICS: General (continued)

Typical values are at $T_A = +25$ °C, AVDD = 1.8 V, LVDD = 1.8 V, 50% clock duty cycle, 100 MSPS, two-wire LVDS interface, and -1-dBFS differential analog input, unless otherwise noted.

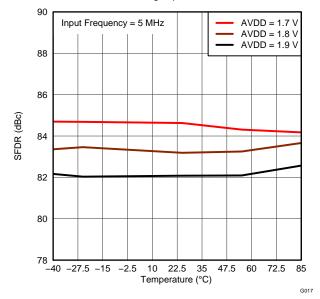


Figure 20. SPURIOUS-FREE DYNAMIC RANGE vs AVDD AND TEMPERATURE

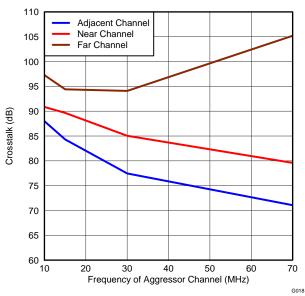


Figure 21. CROSSTALK vs FREQUENCY (1)

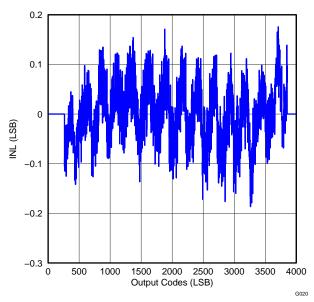


Figure 22. INTEGRAL NONLINEARITY

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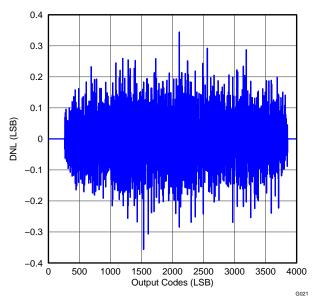


Figure 23. DIFFERENTIAL NONLINEARITY

(1) Adjacent channel: Neighboring channels on the immediate left and right of the channel of interest. Near channel: Channels on the same side of the package, except the immediate neighbors. Far channel: Channels on the opposite side of the package.



TYPICAL CHARACTERISTICS: Digital Processing

Typical values are at $T_A = +25$ °C, AVDD = 1.8 V, LVDD = 1.8 V, 50% clock duty cycle, 100 MSPS, two-wire LVDS interface, and -1-dBFS differential analog input, unless otherwise noted.

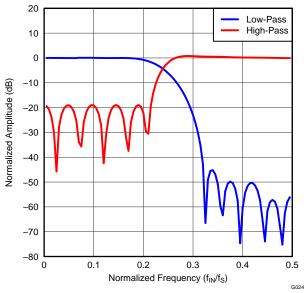


Figure 24. DIGITAL FILTER RESPONSE (Decimate-by-2)

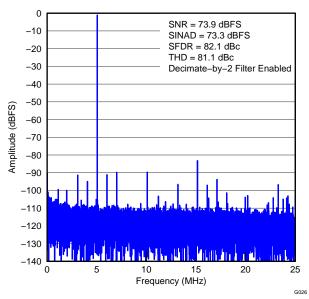
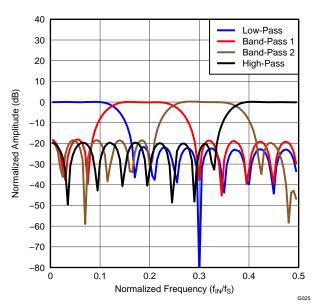


Figure 26. FFT FOR 5-MHz INPUT SIGNAL (Sample Rate = 100 MSPS, Decimation Filter = 2)



NSTRUMENTS

Figure 25. DIGITAL FILTER RESPONSE (Decimate-by-4)

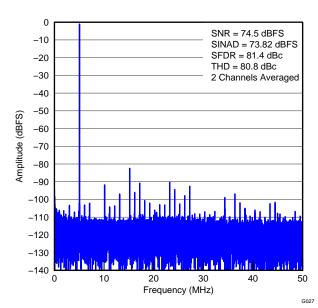


Figure 27. FFT FOR 5-MHz INPUT SIGNAL (Sample Rate = 100 MSPS by Averaging Two Channels)

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TYPICAL CHARACTERISTICS: Digital Processing (continued)

Typical values are at $T_A = +25$ °C, AVDD = 1.8 V, LVDD = 1.8 V, 50% clock duty cycle, 100 MSPS, two-wire LVDS interface, and -1-dBFS differential analog input, unless otherwise noted.

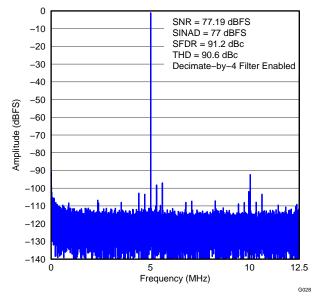


Figure 28. FFT FOR 5-MHz INPUT SIGNAL (Sample Rate = 100 MSPS, Decimation Filter = 4)

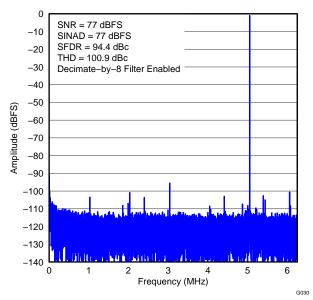


Figure 30. FFT FOR 5-MHz INPUT SIGNAL USING CUSTOM DECIMATION-BY-8 FILTER

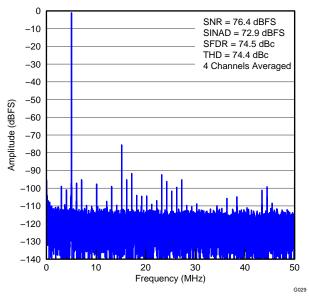


Figure 29. FFT FOR 5-MHz INPUT SIGNAL (Sample Rate = 100 MSPS by Averaging Four Channels)

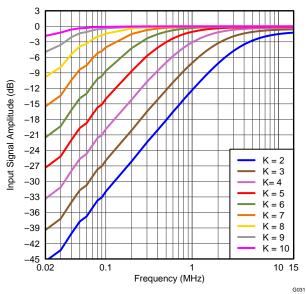


Figure 31. DIGITAL HIGH-PASS FILTER RESPONSE

TEXAS INSTRUMENTS

TYPICAL CHARACTERISTICS: Digital Processing (continued)

Typical values are at $T_A = +25$ °C, AVDD = 1.8 V, LVDD = 1.8 V, 50% clock duty cycle, 100 MSPS, two-wire LVDS interface, and -1-dBFS differential analog input, unless otherwise noted.

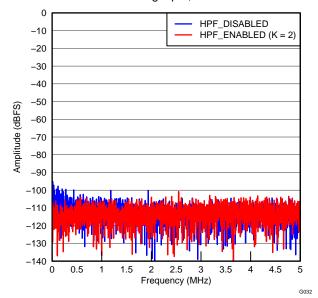


Figure 32. FFT WITH HPF ENABLED AND DISABLED (No Signal)

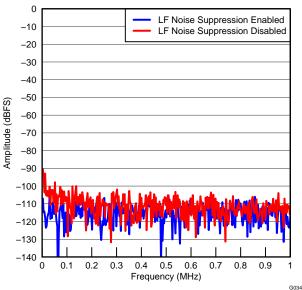


Figure 34. 0-MHz to 1 MHz FFT, 5-MHz INPUT (100-MHz FS with LFNS Enabled)

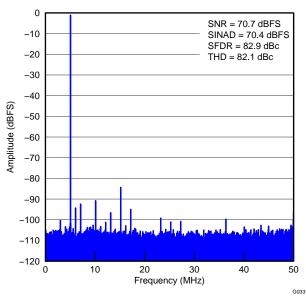


Figure 33. FULL-BAND FFT, 5-MHz INPUT (100-MHz FS with LFNS Enabled)

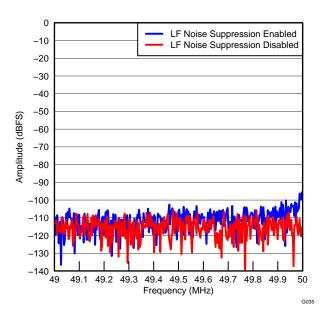


Figure 35. 49-MHz to 50-MHz FFT, 5-MHz INPUT (100-MHz FS with LFNS Enabled)

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TYPICAL CHARACTERISTICS: Power Consumption

Typical values are at $T_A = +25$ °C, AVDD = 1.8 V, LVDD = 1.8 V, 50% clock duty cycle, 100 MSPS, two-wire LVDS interface, and -1-dBFS differential analog input, unless otherwise noted.

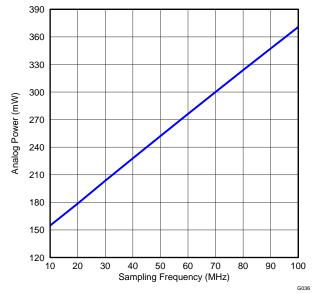


Figure 36. ANALOG SUPPLY POWER

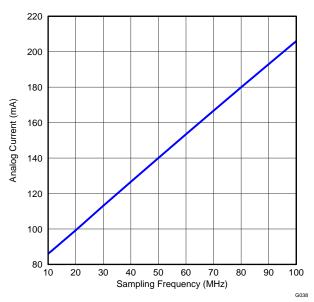


Figure 38. ANALOG SUPPLY CURRENT

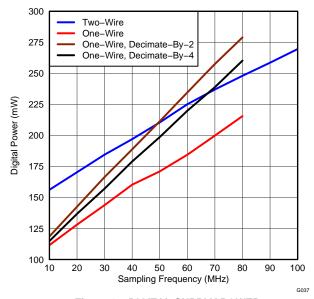


Figure 37. DIGITAL SUPPLY POWER

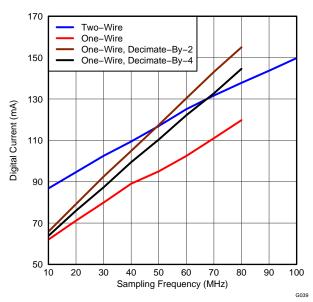


Figure 39. DIGITAL SUPPLY CURRENT



TYPICAL CHARACTERISTICS: Power Consumption (continued)

Typical values are at $T_A = +25$ °C, AVDD = 1.8 V, LVDD = 1.8 V, 50% clock duty cycle, 100 MSPS, two-wire LVDS interface, and -1-dBFS differential analog input, unless otherwise noted.

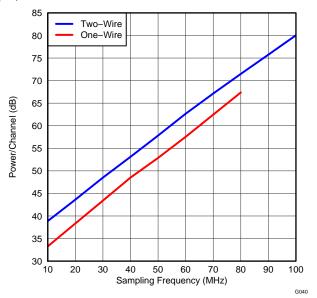


Figure 40. TOTAL POWER PER CHANNEL

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TYPICAL CHARACTERISTICS: Contour

Typical values are at T_A = +25°C, AVDD = 1.8 V, LVDD = 1.8 V, 50% clock duty cycle, 100 MSPS, two-wire LVDS interface, and -1-dBFS differential analog input, unless otherwise noted.

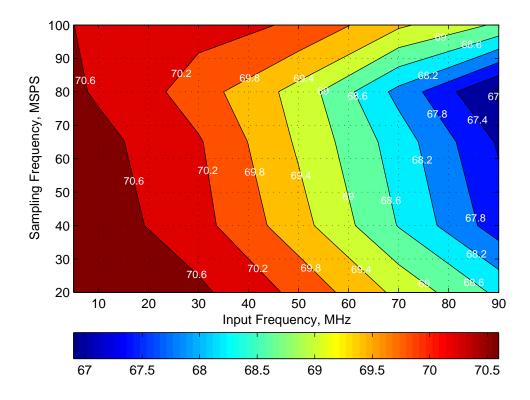


Figure 41. SIGNAL-TO-NOISE RATIO vs INPUT AND SAMPLING FREQUENCIES



TYPICAL CHARACTERISTICS: Contour (continued)

Typical values are at T_A = +25°C, AVDD = 1.8 V, LVDD = 1.8 V, 50% clock duty cycle, 100 MSPS, two-wire LVDS interface, and -1-dBFS differential analog input, unless otherwise noted.

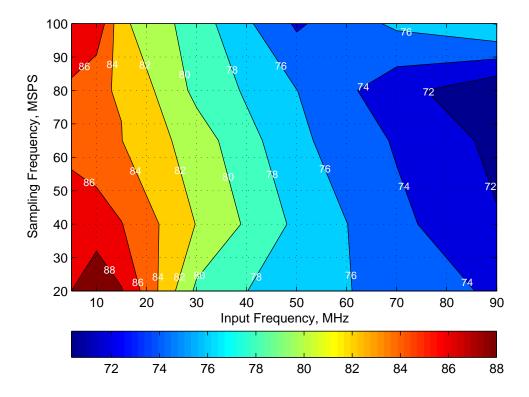


Figure 42. SPURIOUS-FREE DYNAMIC RANGE vs INPUT AND SAMPLING FREQUENCIES

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DEVICE CONFIGURATION

SERIAL INTERFACE

The ADC has a set of internal registers that can be accessed by the serial interface formed by the $\overline{\text{CS}}$ (serial interface enable), SCLK (serial interface clock), and SDATA (serial interface data) pins. Serially shifting bits into the device is enabled when $\overline{\text{CS}}$ is low. The serial data (on the SDATA pin) are latched at every SCLK falling edge when $\overline{\text{CS}}$ is active (low). The serial data are loaded into the register at every 24th SCLK rising edge when $\overline{\text{CS}}$ is low. When the word length exceeds a multiple of 24 bits, the excess bits are ignored. Data can be loaded in multiples of 24-bit words within a single active $\overline{\text{CS}}$ pulse. The first eight bits form the register address and the remaining 16 bits are the register data. The interface can function with SCLK frequencies from 15 MHz down to very low speeds (of a few hertz) and also with a non-50% SCLK duty cycle.

Register Initialization

After power-up, the internal registers must be initialized to default values. This initialization can be accomplished in one of two ways:

- 1. Either through a hardware reset by applying a high pulse on the RESET pin (of widths greater than 10 ns), as shown in Figure 43; or
- 2. By applying a software reset. When using the serial interface, set the RESET bit (register 00h, bit D7) high. This setting initializes the internal registers to default values and then self-resets the RESET bit low. In this case, the RESET pin is kept low (inactive).

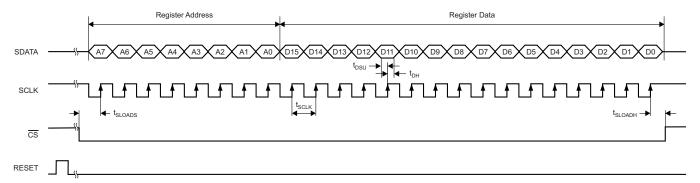


Figure 43. Serial Interface Timing Diagram

Table 5. Timing Characteristics for Figure 43⁽¹⁾

	PARAMETER	MIN	TYP	MAX	UNIT
f _{SCLK}	SCLK frequency (equal to 1 / t _{SCLK})	>dc		15	MHz
t _{SLOADS}	CS to SCLK setup time	33			ns
t _{SLOADH}	SCLK to CS hold time	33			ns
t _{DSU}	SDATA setup time	33			ns
t _{DH}	SDATA hold time	33			ns

(1) Typical values are at T_A = +25°C, minimum and maximum values are across the full temperature range of T_{MIN} = -40°C to T_{MAX} = +85°C, unless otherwise noted.

TEXAS INSTRUMENTS

Reset Timing

Figure 44 shows a timing diagram for the reset function.

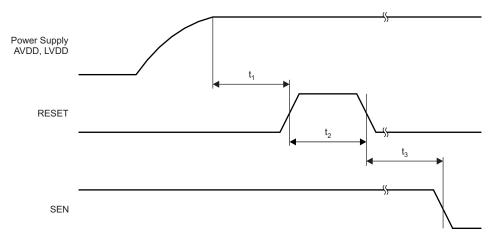


Figure 44. Reset Timing Diagram

Table 6. Timing Characteristics for Figure 44⁽¹⁾⁽²⁾

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t ₁	Power-on delay	Delay from AVDD and LVDD power-up to active RESET pulse	1			ms
t ₂	Reset pulse width	Pulse width of active RESET signal	50			ns
t ₃	Register write delay	Delay from RESET disable to CS active		100		ns

⁽¹⁾ Typical values are at $T_A = +25^{\circ}$ C, minimum and maximum values are across the full temperature range of $T_{MIN} = -40^{\circ}$ C to $T_{MAX} = +85^{\circ}$ C, unless otherwise noted.

⁽²⁾ A high pulse on the RESET pin is required when initialization is done via a hardware reset.

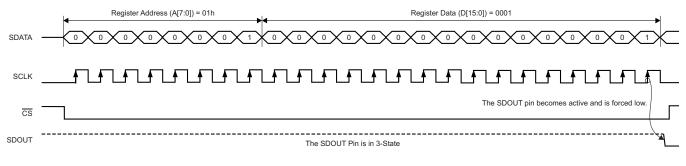
Serial Register Readout

The device includes a mode where the contents of the internal registers can be read back on the SDOUT pin. This readback mode may be useful as a diagnostic check to verify the serial interface communication between the external controller and the ADC.

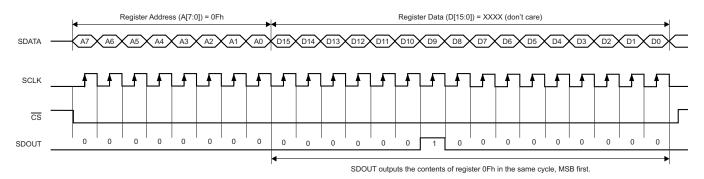
By default, the SDOUT pin is in 3-state after a device power-up or reset. When the readout mode is enabled using the READOUT register bit, SDOUT serially outputs the contents of the selected register. The following steps describe how to achieve this functionality:

- 1. Set the READOUT register bit to '1'. This setting puts the device in serial readout mode. This mode prevents any further writes to the internal registers, *except* for at register 01h. Note that the READOUT bit is also located in register 01h. The device can exit readout mode by setting the READOUT bit to '0'. Note that only the contents of register 01h are unable to be read in register readout mode.
- 2. Initiate a serial interface cycle specifying the address of the register (A[7:0]) whose content must be read.
- 3. The device serially outputs the contents (D[15:0]) of the selected register on the SDOUT pin.
- 4. The external controller can latch the contents at the SCLK rising edge.

To exit serial readout mode, reset the READOUT register bit to '0', which enables writes to all device registers. At this point, the SDOUT pin is in 3-state. A detailed timing diagram for the serial readout mode is shown in Figure 45.



a) Enable Serial Readout (READOUT = 1)



b) Read contents of register 0Fh. This register is initialized with 0200 (the device was previously put in global power-down).

Figure 45. Serial Readout Timing Diagram



SERIAL INTERFACE REGISTERS MAP

Table 7 lists the ADS5295 registers.

Table 7. Register Map

REGISTER																
ADDRESS (Hex)	D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
00	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	RST
01	0	0	0	0	0	0	0	0	0	0	0	EN_HIGH_ ADDRS	0	0	0	EN_ READOUT
0A				1				RAMP_PAT_	RESET_VAL							
0F	0	0	0	0	0	PDN_PIN_ CFG	PDN_ COMPLETE	PDN_ PARTIAL				PDN_0	CH[8:1]			
14	0	0	0	0	0	0	0	0				LFNS_	CH[8:1]			
1C	0	EN_FRAME _PAT	0	0						ADCLK	OUT[11:0]					
23								PRBS_SE	EED[15:0]							
24		ı	PI	RBS_SEED[22:	16]			0		1		INVERT	_CH[8:1]		T	
25	TP_HARD_ SYNC	PRBS_ SEED_ FROM_REG	PRBS_ MODE_2	PRBS_ TP_EN	0	0	0	TP_SOFT_ SYNC	0		TEST_PATT[2:	0]	BITS_CUS	STOM2[11:10]	BITS_CUS	TOM1[11:10]
26					BITS_CU	STOM1[9:0]					0	0	0	0	0	0
27					BITS_CU	STOM2[9:0]					0	0	0	0	0	0
28	EN_WORD _BIT_WISE	0	0	0	0	0	0	EN_BIT _WISE	EN_WORDWISE_BY_CI			SE_BY_CH[7:	0]			
29	0	0	0	0	0	0	0	0	0	0	0	0	0	0	EN_DIG_ FILTER	EN_ CHANNEL_ AVG
2A		GAIN_C	CH4[3:0]			GAIN_	CH3[3:0]			GAIN_	CH2[3:0]			GAIN_0	CH1[3:0]	
2B		GAIN_C	CH5[3:0]			GAIN_	CH6[3:0]			GAIN_	CH7[3:0]			GAIN_0	CH8[3:0]	
2C	0	0	0	0	0	AVG_C	DUT4[1:0]	0	AVG_C	UT3[1:0]	0	AVG_O	UT2[1:0]	0	AVG_C	OUT1[1:0]
2D	0	0	0	0	0	AVG_C	OUT8[1:0]	0	AVG_C	UT7[1:0]	0	AVG_O	UT6[1:0]	0	AVG_C	OUT5[1:0]
2E	0	HPF_EN_ CH1		HPF_CORN	ER_CH1[3:0]		FILT	ER_TYPE_CH1	1[2:0]	ı	DEC_RATE_C	H1	0	SEL_ODD_ TAP_CH1	0	USE_ FILTER_ CH1
2F	0	HPF_EN_ CH2		HPF_CORN	ER_CH2[3:0]		FILT	ER_TYPE_CH2	2[2:0]	1	DEC_RATE_C	H2	0	SEL_ODD_ TAP_CH2	0	USE_ FILTER_ CH2
30	0	HPF_EN_ CH3		HPF_CORN	ER_CH3[3:0]		FILT	ER_TYPE_CH	3[2:0]		DEC_RATE_C	H3	0	SEL_ODD_ TAP_CH3	0	USE_ FILTER_ CH3
31	0	HPF_EN_ CH4		HPF_CORN	ER_CH4[3:0]	H4[3:0] FILTER_TYPE_CH			4[2:0]	1	DEC_RATE_C	H4	0	SEL_ODD_ TAP_CH4	0	USE_ FILTER_ CH4
32	0	HPF_EN_ CH5		HPF_CORN	ER_CH5[3:0]	H5[3:0] FILTER_TYPE_CH			5[2:0]	1	DEC_RATE_C	H5	0	SEL_ODD_ TAP_CH5	0	USE_ FILTER_ CH5
33	0	HPF_EN_ CH6		HPF_CORN	ER_CH6[3:0]		FILT	ER_TYPE_CH6	6[2:0]		DEC_RATE_C	H6	0	SEL_ODD_ TAP_CH6	0	USE_ FILTER_ CH6



Table 7. Register Map (continued)

REGISTER ADDRESS (Hex)	D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
34	0	HPF_EN_ CH7			ER_CH7[3:0]			ER_TYPE_CH	7[2:0] DEC_RATE_CH7				0	SEL_ODD_ TAP_CH7	0	USE_ FILTER_ CH7
35	0	HPF_EN_ CH8		HPF_CORN	ER_CH8[3:0]		FILT	ER_TYPE_CH	CH8[2:0] DEC_RATE_CH8		18	0	SEL_ODD_ TAP_CH8	0	USE_ FILTER_ CH8	
38	0	0	0	0	0	0	0	0	0	0	0	0	0	0	DATA_F	RATE[1:0]
42	EN_PHASE DDR	0	0	0	0	0	0	0	0	PHASE_ DDR1	PHASE_ DDR0	0	0	0	0	0
45	0	0	0	0	0	0	0	0	0	0	0	0	0	0	PAT_DESKE	:W_SYNC[1:0]
46	ENABLE 46	0	FALL_SDR	0		BIT_S	ER_SEL	1	0	0	0	EN_SDR	EN_MSB_ FIRST	BTC_MODE	0	EN_2WIRE
50	ENABLE 50	0	0	0		MAP_Ch12	34_to_OUT2A			MAP_Ch123	34_to_OUT1B			MAP_Ch123	34_to_OUT1A	1
51	ENABLE 51	0	0	0		MAP_Ch12	34_to_OUT3B			MAP_Ch123	34_to_OUT3A			MAP_Ch123	34_to_OUT2B	
52	ENABLE 52	0	0	0	0	0	0	0		MAP_Ch12	34_to_OUT4B			MAP_Ch123	34_to_OUT4A	
53	ENABLE 53	0	0	0		MAP_Ch5678_to_OUT6B MAP_Ch5678_to_OUT5A						MAP_Ch567	78_to_OUT5B			
54	ENABLE 54	0	0	0		MAP_Ch5678_to_OUT7B MAP_Ch5678_to_OUT7B				MAP_Ch5678_to_OUT6A						
55	ENABLE 55	0	0	0	0	0	0	0		MAP_Ch567	78_to_OUT8A			MAP_Ch567	'8_to_OUT8B	
5A to 65	EN_ CUSTOM_ FILT_CH1	0	0	0		COEFFn_SET_CH1 ⁽¹⁾										
66 to 71	EN_ CUSTOM_ FILT_CH2	0	0	0						COEFFn_	SET_CH2 ⁽¹⁾					
72 to 7D	EN_ CUSTOM_ FILT_CH3	0	0	0						COEFFn_	SET_CH3 ⁽¹⁾					
7E to 89	EN_ CUSTOM_ FILT_CH4	0	0	0						COEFFn_	SET_CH4 ⁽¹⁾					
8A to 95	EN_ CUSTOM_ FILT_CH5	0	0	0						COEFFn_	SET_CH5 ⁽¹⁾					
96 to A1	EN_ CUSTOM_ FILT_CH6	0	0	0						COEFFn_	SET_CH6 ⁽¹⁾					
A2 to AD	EN_ CUSTOM_ FILT_CH7	0	0	0		COEFFn_SET_CH7 ⁽¹⁾										
AE to B9	EN_ CUSTOM_ FILT_CH8	0	0	0	COEFF <i>n_</i> SET_CH8 ⁽¹⁾											
BE	EN_LVDS _PROG	0	0	0	0 0 DELAY_DATA_R DELAY_LCLK_R DELAY_DATA_F DELAY_LC				DELAY_LCLK_	F						
F0	EN_EXT_ REF	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0

⁽¹⁾ n = 0 to 11.

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DESCRIPTION OF SERIAL INTERFACE REGISTERS

Register 00h

D15	D14	D13	D12	D11	D10	D9	D8
0	0	0	0	0	0	0	0
D7	D6	D5	D4	D3	D2	D1	D0
0	0	0	0	0	0	0	RST

Bits D[15:1] Must write '0'

Bit D0 RST

0 = Normal operation (default)

1 = Self-clearing software RESET; after reset, this bit is set to '0'

Register 01h

D15	D14	D13	D12	D11	D10	D9	D8
0	0	0	0	0	0	0	0
D7	D6	D5	D4	D3	D2	D1	D0
0	0	0	EN_HIGH_ ADDRS	0	0	0	EN_READOUT

Bits D[15:5] Must write '0'

Bit D4 EN_HIGH_ADDRS

0 = Access to register F0h disabled (default)

1 = Access to register F0h enabled

Bits D[3:1] Must write '0'
Bit D0 EN_READOUT

0 = Normal operation (default)

1 = READOUT of registers mode using the SDOUT pin enabled

Register 0Ah

D15	D14	D13	D12	D11	D10	D9	D8				
			RAMP_PAT_	_RESET_VAL							
D7	D6	D5	D4	D3	D2	D1	D0				
	RAMP_PAT_RESET_VAL										

Bits D[15:0] RAMP_PAT_RESET_VAL

The starting value of digital ramp test pattern can be programmed using these register bits. By default, after a reset, the starting value is 0000h.



Register 0Fh

D15	D14	D13	D12	D11	D10	D9	D8				
0	0	0	0	0	PDN_PIN_CFG	PDN_ COMPLETE	PDN_PARTIAL				
D7	D6	D5	D4	D3	D2	D1	D0				
	PDN_CH[8:1]										

All bits default to '0' after reset.

Bits D[15:11] Must write '0'
Bit D10 PDN_PIN_CFG

0 = PD pin configured for complete power-down mode 1 = PD pin configured for partial power-down mode

Bit D9 PDN_COMPLETE

0 = Normal operation

1 = Register mode for complete power-down; slow recovery from power-down

Bit D8 PDN_PARTIAL

0 = Normal operation

1 = Partial power-down mode; fast recovery from power-down

Bits D[7:0] PDN_CH[8:1]

0 = Normal operation

1 = Individual channel ADC power-down mode

Register 14h

D15	D14	D13	D12	D11	D10	D9	D8				
0	0	0	0	0	0	0	0				
D7	D6	D5	D4	D3	D2	D1	D0				
	LFNS_CH[8:1]										

Bits D[7:0] Must write '0'

Bits D[7:0] LFNS_CH[8:1]

0 = LFNS disabled (default)

1 = Low-frequency noise suppression (LFNS) mode enabled for individual channels



Register 1Ch

D15	D14	D13	D12	D11	D10	D9	D8			
0	EN_FRAME_ PAT	0	0		ADCLKO	UT[11:0]				
D7	D6	D5	D4	D3	D2	D1	D0			
ADCLKOUT[11:0]										

All bits default to '0' after reset.

Bit D15 Must write '0'
Bit D14 EN FRAME PAT

0 = Normal operation on frame clock (default)

1 = Enables output frame clock to be programmed through a pattern specified by

ADCCLKOUT register bits

Bits D[13:12] Must write '0'
Bits D[11:0] ADCLKOUT[11:0]

These bits create the 12-bit pattern for the frame clock on the ADCLKP, ADCLKN pins.

Register 23h

D15	D14	D13	D12	D11	D10	D9	D8		
PRBS_SEED[15:0]									
D7	D6	D5	D4	D3	D2	D1	D0		
PRBS_SEED[15:0]									

Bits D[15:0] PRBS_SEED[15:0]

These bits are the lower 16 bits of the PRBS pattern starting seed value.

The starting seed value of the PRBS test pattern can be specified using these register bits

Register 24h

D15	D14	D13	D12	D11	D10	D9	D8	
PRBS_SEED[22:16]							0	
D7	D6	D5	D4	D3	D2	D1	D0	
INVERT_CH[8:1]								

All bits default to '0' after reset.

Bits D[15:9] PRBS_SEED[22:16]

These bits are the seven upper bits of the PRBS seed starting value.

Bit D8 Must write '0'
Bits D[7:0] INVERT_CH[8:1]

0 = Normal configuration

Normally, the INP pin represents the positive analog input pin and INN represents the complementary negative input.

1 = The polarity of the analog input pins is electrically swapped

Setting the INVERT_CH[8:1] bits causes the inputs to be swapped. INN now represents the

positive input and INP represents the negative input.

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Register 25h

D15	D14	D13	D12	D11	D10	D9	D8
TP_HARD_ SYNC	PRBS_SEED_ FROM_REG	PRBS_ MODE_2	PRBS_TP_EN	0	0	0	TP_SOFT_ SYNC
D7	D6	D5	D4	D3	D2	D1	D0
0		TEST_PATT[2:0]			OM2[11:10]	BITS_CUST	TOM1[11:10]

All bits default to '0' after reset.

Bit D15 TP HARD SYNC

0 = Inactive

1 = The external SYNC feature is enabled for syncing test patterns

PRBS_SEED_FROM_REG Bit D14

0 = Disabled

1 = The PRBS seed is now able to be chosen from registers 23h and 24h

Bit D13 PRBS MODE 2

The PRBS 9-bit LFSR (23-bit LFSR) is the default mode.

Bit D12 PRBS_TP_EN

> 0 = PRBS test pattern disabled 1 = PRBS test pattern enabled

Bits D[11:9] Must write '0'

Bit D8 TP SOFT SYNC

0 = No svnc

1 = Software sync bit for the test patterns on all eight channels

Bit D7 Must write '0' **TEST PATT2** Bit D6

0 = Normal operation

1 = A repeating full-scale ramp pattern is enabled on the outputs; ensure that bits D4 and

D5 are '0'

Bit D5 **TEST PATT1**

0 = Normal operation

1 = Enables a mode where the output toggles between two defined codes; ensure that bits

D4 and D6 are '0'

Bit D4 TEST_PATT0

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0 = Normal operation

1 = Enables a mode where the output is a constant specified code; ensure that bits D5 and

D6 are '0'

Bits D[3:2] **BITS CUSTOM2[11:10]**

These bits are the two MSBs for the second code of the dual custom patterns.

Bits D[1:0] **BITS CUSTOM1[11:10]**

These bits are the two MSBs for the single custom pattern (and for the first code of the dual

custom patterns).



Register 26h

D15	D14	D13	D12	D11	D10	D9	D8	
BITS_CUSTOM1[9:0]								
D7	D6	D5	D4	D3	D2	D1	D0	
BITS_CUSTOM1[9:0] 0		0	0	0	0	0	0	

Bits D[15:6] BITS_CUSTOM1[9:0]

These bits are the 10 lower bits for the single custom pattern (and for the first code of the dual custom pattern).

Bits D[5:0] Must write '0'

Register 27h

D15	D14	D13	D12	D11	D10	D9	D8		
BITS_CUSTOM2[9:0]									
D7	D6	D5	D4	D3	D2	D1	D0		
BITS_CUSTOM2[9:0]		0	0	0	0	0	0		

Bits D[15:6] BITS_CUSTOM2[9:0]

These bits are the 10 lower bits for the second code of the dual custom pattern.

Bits D[5:0] Must write '0'



Register 28h

D15	D14	D13	D12	D11	D10	D9	D8		
EN_WORD_ BIT_WISE	0	0	0	0	0	0	EN_BIT_WISE		
D7	D6	D5	D4	D3	D2	D1	D0		
EN_WORDWISE_BY_CH[7:0]									

All bits default to '0' after reset.

Bit D15 EN_WORD_BIT_WISE

This bit enables the bit order output in two-wire mode.

0 = Byte-wise

1 = Word-wise if D[7:0] = 1 (bit-wise if D8 = 1 and D[7:0] = 0)

Bits D[14:9] Must write '0'
Bit D8 EN_BIT_WISE

1 = Bit-wise if D15 = 1 and D[7:0] = 0

Bits D[7:0] EN_WORDWISE_BY_CH[7:0]

0 = Bit-wise if D15 = 1 and D8 = 1

1 = Word-wise if D15 = 1

Register 29h

D15	D14	D13	D12	D11	D10	D9	D8
0	0	0	0	0	0	0	0
D7	D6	D5	D4	D3	D2	D1	D0
0	0	0	0	0	0	EN_DIG_ FILTER	EN_CHANNEL _AVG

Bits D[15:2] Must write '0'
Bit D1 EN_DIG_FILTER

0 = Global control digital filter disabled(default)

1 = Global control digital filter enabled

Bit D0 EN_CHANNEL_AVG

0 = Channel averaging is disabled (default)

1 = Channel averaging is enabled and specified by the AVG_OUT*n* register bits



Register 2Ah

D15	D14	D13	D12	D11	D10	D9	D8
	GAIN_C	CH4[3:0]			GAIN_C	H3[3:0]	
D7	D6	D5	D4	D3	D2	D1	D0
GAIN_CH2[3:0] GAIN_CH1[3:0]							

Bits D[15:12] GAIN_CH4[3:0]

These bits set the programmable gain for channel 4.

Bits D[11:8] GAIN_CH3[3:0]

These bits set the programmable gain for channel 3.

Bits D[7:4] GAIN_CH2[3:0]

These bits set the programmable gain for channel 2.

Bits D[3:0] GAIN_CH1[3:0]

These bits set the programmable gain for channel 1.

Register 2Bh

D15	D14	D13	D12	D11	D10	D9	D8
	GAIN_C	CH5[3:0]			GAIN_C	H6[3:0]	
D7	D6	D5	D4	D3	D2	D1	D0
	GAIN_C	CH7[3:0]			GAIN_C	:H8[3:0]	

Bits D[15:12] GAIN_CH5[3:0]

These bits set the programmable gain for channel 5.

Bits D[11:8] GAIN_CH6[3:0]

These bits set the programmable gain for channel 6.

Bits D[7:4] GAIN_CH7[3:0]

These bits set the programmable gain for channel 7.

Bits D[3:0] GAIN_CH8[3:0]

These bits set the programmable gain for channel 8.



Register 2Ch

D15	D14	D13	D12	D11	D10	D9	D8
0	0	0	0	0	AVG_OL	JT4[1:0]	0
D7	D6	D5	D4	D3	D2	D1	D0
AVG_O	UT3[1:0]	0	AVG_O	UT2[1:0]	0	AVG_O	UT1[1:0]

Bits D[15:11] Must write '0'
Bits D[10:9] AVG_OUT4[1:0]

These bits set the averaging control for what is transmitted on the LVDS output OUT4.

Bit D8 Must write '0'
Bits D[7:6] AVG_OUT3[1:0]

These bits set the averaging control for what is transmitted on the LVDS output OUT3.

Bit D5 Must write '0'
Bits D[4:3] AVG_OUT2[1:0]

These bits set the averaging control for what is transmitted on the LVDS output OUT2.

Bit D2 Must write '0'
Bits D[1:0] AVG_OUT1[1:0]

These bits set the averaging control for what is transmitted on the LVDS output OUT1.

Register 2Dh

D15	D14	D13	D12	D11	D10	D9	D8
0	0	0	0	0	AVG_OL	JT8[1:0]	0
D7	D6	D5	D4	D3	D2	D1	D0
AVG O	UT7[1:0]	0	AVG O	UT6[1:0]	0	AVG OL	JT5[1:0]

Bits D[15:11] Must write '0'
Bits D[10:9] AVG_OUT8[1:0]

These bits set the averaging control for what is transmitted on the LVDS output OUT8.

Bit D8 Must write '0'
Bits D[7:6] AVG_OUT7[1:0]

These bits set the averaging control for what is transmitted on the LVDS output OUT7.

Bit D5 Must write '0'
Bits D[4:3] AVG_OUT6[1:0]

These bits set the averaging control for what is transmitted on the LVDS output OUT6.

Bit D2 Must write '0'
Bits D[1:0] AVG_OUT5[1:0]

These bits set the averaging control for what is transmitted on the LVDS output OUT5.



Register 2Eh

D15	D14	D13	D12	D11	D10	D9	D8
0	HPF_EN_CH1		HPF_CORNI	ER _CH1[3:0]		FILTER_TY	PE_CH1[2:0]
D7	D6	D5	D4	D3	D2	D1	D0
FILTER_TYPE _CH1[2:0]	DE	EC_RATE_CH1[2	2:0]	0	SEL_ODD_ TAP_CH1	0	USE_FILTER_ CH1

Bit D15 Must write '0'
Bit D14 HPF_EN_CH1

This bit enables the HPF filter for channel 1.

Bits D[13:10] HPF_CORNER _CH1[3:0]

These bits program the HPF corner for channel 1.

Bits D[9:7] FILTER_TYPE_CH1[2:0]

These bits select the type of filter on channel 1.

Bits D[6:4] DEC_RATE_CH1[2:0]

These bits set the decimation factor for the filter on channel 1.

Bit D3 Must write '0'

Bit D2 SEL_ODD_TAP_CH1

This bit enables the odd tap filter for channel 1.

Bit D1 Must write '0'

Bit D0 USE_FILTER_CH1

This bit enables the filter for channel 1.

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Register 2Fh

D15	D14	D13	D12	D11	D10	D9	D8
0	HPF_EN_CH2		HPF_CORN	ER _CH2[3:0]		FILTER_TY	PE_CH2[2:0]
D7	D6	D5	D4	D3	D2	D1	D0
FILTER_TYPE _CH2[2:0]	DE	C_RATE_CH2[2:0]	0	SEL_ODD_ TAP_CH2	0	USE_FILTER_ CH2

Bit D15 Must write '0' Bit D14 HPF_EN_CH2

This bit enables the HPF filter for channel 2.

Bits D[13:10] HPF_CORNER _CH2[3:0]

These bits program the HPF corner for channel 2.

Bits D[9:7] FILTER_TYPE_CH2[2:0]

These bits select the type of filter on channel 2.

Bits D[6:4] DEC_RATE_CH2[2:0]

These bits set the decimation factor for the filter on channel 2.

Bit D3 Must write '0'

Bit D2 SEL_ODD_TAP_CH2

This bit enables the odd tap filter for channel 2.

Must write '0' Bit D1

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Bit D0 USE_FILTER_CH2

This bit enables the filter for channel 2.



Register 30h

D15	D14	D13	D12	D11	D10	D9	D8
0	HPF_EN_CH3		HPF_CORNI	ER _CH3[3:0]		FILTER_TY	PE_CH3[2:0]
D7	D6	D5	D4	D3	D2	D1	D0
FILTER_TYPE _CH3[2:0]	DE	EC_RATE_CH3[2	2:0]	0	SEL_ODD_ TAP_CH3	0	USE_FILTER_ CH3

Bit D15 Must write '0'
Bit D14 HPF_EN_CH3

This bit enables the HPF filter for channel 3.

Bits D[13:10] HPF_CORNER _CH3[3:0]

These bits program the HPF corner for channel 3.

Bits D[9:7] FILTER_TYPE_CH3[2:0]

These bits select the type of filter on channel 3.

Bits D[6:4] DEC_RATE_CH3[2:0]

These bits set the decimation factor for the filter on channel 3.

Bit D3 Must write '0'

Bit D2 SEL_ODD_TAP_CH3

This bit enables the odd tap filter for channel 3.

Bit D1 Must write '0'

Bit D0 USE_FILTER_CH3

This bit enables the filter for channel 3.

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Register 31h

D15	D14	D13	D12	D11	D10	D9	D8
0	HPF_EN_CH4		HPF_CORN	ER _CH4[3:0]		FILTER_TY	PE_CH4[2:0]
D7	D6	D5	D4	D3	D2	D1	D0
FILTER_TYPE _CH4[2:0]	DE	EC_RATE_CH4[2	2:0]	0	SEL_ODD_ TAP_CH4	0	USE_FILTER_ CH4

Bit D15 Must write '0'
Bit D14 HPF_EN_CH4

This bit enables the HPF filter for channel 4.

Bits D[13:10] HPF_CORNER _CH4[3:0]

These bits program the HPF corner for channel 4.

Bits D[9:7] FILTER_TYPE_CH4[2:0]

These bits select the type of filter on channel 4.

Bits D[6:4] DEC_RATE_CH4[2:0]

These bits set the decimation factor for the filter on channel 4.

Bit D3 Must write '0'

Bit D2 SEL_ODD_TAP_CH4

This bit enables the odd tap filter for channel 4.

Bit D1 Must write '0'

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Bit D0 USE_FILTER_CH4

This bit enables the filter for channel 4.



Register 32h

D15	D14	D13	D12	D11	D10	D9	D8
0	HPF_EN_CH5		HPF_CORN	ER _CH5[3:0]		FILTER_TY	PE_CH5[2:0]
D7	D6	D5	D4	D3	D2	D1	D0
FILTER_TYPE _CH5[2:0]	DE	EC_RATE_CH5[2	2:0]	0	SEL_ODD_ TAP_CH5	0	USE_FILTER_ CH5

Bit D15 Must write '0'
Bit D14 HPF_EN_CH5

This bit enables the HPF filter for channel 5.

Bits D[13:10] HPF_CORNER _CH5[3:0]

These bits program the HPF corner for channel 5.

Bits D[9:7] FILTER_TYPE_CH5[2:0]

These bits select the type of filter on channel 5.

Bits D[6:4] DEC_RATE_CH5[2:0]

These bits set the decimation factor for the filter on channel 5.

Bit D3 Must write '0'

Bit D2 SEL_ODD_TAP_CH5

This bit enables the odd tap filter for channel 5.

Bit D1 Must write '0'

Bit D0 USE_FILTER_CH5

This bit enables the filter for channel 5.



Register 33h

D15	D14	D13	D12	D11	D10	D9	D8
0	HPF_EN_CH6		HPF_CORN	ER _CH6[3:0]		FILTER_TY	PE_CH6[2:0]
D7	D6	D5	D4	D3	D2	D1	D0
FILTER_TYPE _CH6[2:0]	DE	EC_RATE_CH6[2:0]	0	SEL_ODD_ TAP_CH6	0	USE_FILTER_ CH6

Bit D15 Must write '0'
Bit D14 HPF_EN_CH6

This bit enables the HPF filter for channel 6.

Bits D[13:10] HPF_CORNER _CH6[3:0]

These bits program the HPF corner for channel 6.

Bits D[9:7] FILTER_TYPE_CH6[2:0]

These bits select the type of filter on channel 6.

Bits D[6:4] DEC_RATE_CH6[2:0]

These bits set the decimation factor for the filter on channel 6.

Bit D3 Must write '0'

Bit D2 SEL_ODD_TAP_CH6

This bit enables the odd tap filter for channel 6.

Bit D1 Must write '0'

Bit D0 USE_FILTER_CH6

This bit enables the filter for channel 6.



Register 34h

D15	D14	D13	D12	D11	D10	D9	D8	
0	HPF_EN_CH7		HPF_CORN	ER _CH7[3:0]		FILTER_TYPE_CH7[2:0]		
D7	D6	D5	D4	D3	D2	D1	D0	
FILTER_TYPE _CH7[2:0]	DEC_RATE_CH7[2:0]			0	SEL_ODD_ TAP_CH7	0	USE_FILTER_ CH7	

Bit D15 Must write '0'
Bit D14 HPF_EN_CH7

This bit enables the HPF filter for channel 7.

Bits D[13:10] HPF_CORNER _CH7[3:0]

These bits program the HPF corner for channel 7.

Bits D[9:7] FILTER_TYPE_CH7[2:0]

These bits select the type of filter on channel 7.

Bits D[6:4] DEC_RATE_CH7[2:0]

These bits set the decimation factor for the filter on channel 7.

Bit D3 Must write '0'

Bit D2 SEL_ODD_TAP_CH7

This bit enables the odd tap filter for channel 7.

Bit D1 Must write '0'

Bit D0 USE_FILTER_CH7

This bit enables the filter for channel 7.

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Register 35h

D15	D14	D13	D12	D11	D10	D9	D8
0	HPF_EN_CH8		HPF_CORN	ER _CH8[3:0]		FILTER_TY	PE_CH8[2:0]
D7	D6	D5	D4	D3	D2	D1	D0
FILTER_TYPE _CH8[2:0]	DI	EC_RATE_CH8[2:0]	0	SEL_ODD_ TAP_CH8	0	USE_FILTER_ CH8

Bit D15 Must write '0'
Bit D14 HPF_EN_CH8

This bit enables the HPF filter for channel 8.

Bits D[13:10] HPF_CORNER _CH8[3:0]

These bits program the HPF corner for channel 8.

Bits D[9:7] FILTER_TYPE_CH8[2:0]

These bits select the type of filter on channel 8.

Bits D[6:4] DEC_RATE_CH8[2:0]

These bits set the decimation factor for the filter on channel 8.

Bit D3 Must write '0'

Bit D2 SEL_ODD_TAP_CH8

This bit enables the odd tap filter for channel 8.

Bit D1 Must write '0'

Bit D0 USE_FILTER_CH8

This bit enables the filter for channel 8.

Register 38h

D15	D14	D13	D12	D11	D10	D9	D8
0	0	0	0	0	0	0	0
D7	D6	D5	D4	D3	D2	D1	D0
0	0	0	0	0	0	DATA_R	ATE[1:0]

Bits D[15:2] Must write '0'

Bits D[1:0] DATA_RATE[1:0]

Bits D1 and D0 select the output data rate depending on the type of filter.



Register 42h

D15	D14	D13	D12	D11	D10	D9	D8
EN_PHASE_ DDR	0	0	0	0	0	0	0
D7	D6	D5	D4	D3	D2	D1	D0
0	PHASE_DDR1	PHASE_DDR0	0	0	0	0	0

Bit D15 This bit enables LCLK phase programmability.

Bits D[14:7] Must write '0'
Bits D[6:5] PHASE_DDR[1:0]

These bits control the LCLK output phase relative to data.

Refer to the Programmable LCLK Phase section.

Bits D[4:0] Must write '0'

Register 45h

D15	D14	D13	D12	D11	D10	D9	D8
0	0	0	0	0	0	0	0
D7	D6	D5	D4	D3	D2	D1	D0
0	0	0	0	0	0	PAT_DESKE	W_SYNC[1:0]

Bits D[15:2] Must write '0'

Bit D1 PAT_DESKEW_SYNC1

0 = Inactive

1 = Sync pattern mode enabled; ensure that D0 is '0'

Bit D0 PAT_DESKEW_SYNC0

0 = Inactive

1 = Deskew pattern mode enabled; ensure that D1 is '0'

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Register 46h

D15	D14	D13	D12	D11	D10	D9	D8
ENABLE 46	0	FALL_SDR	0		BIT_SE	R_SEL	
D7	D6	D5	D4	D3	D2	D1	D0
0	0	0	EN_SDR	EN_MSB_ FIRST	BTC_MODE	0	EN_2WIRE

All bits default to '0' after reset. Note that bit D15 must be set to '1' to enable bits D[13:0].

Bit D15 ENABLE 46

This bit enables register 46h.

Bit D14 Must write '0'
Bit D13 FALL SDR

0 =The LCLK rising or falling edge comes at the edge of the data window when operating in

SDR output mode

1 = The LCLK rising or falling edge comes in the middle of the data window when operating

in SDR output mode

Bit D12 Must write '0'
Bits D[11:8] BIT_SER_SEL

0001 = 10-bit serialization mode enabled 0010 = 12-bit serialization mode enabled 0100 = 14-bit serialization mode enabled 1000 = 16-bit serialization mode enabled Do not use any other bit combinations.

Bits D[7:5] Must write '0'

Bit D4 EN_SDR

0 = DDR bit clock 1 = SDR bit clock

Bit D3 EN_MSB_FIRST

0 = LSB first 1 = MSB first

Bit D2 BTC MODE

0 = Binary offset (ADC data output format)

1 = Twos complement (ADC data output format)

Bit D1 Must write '0'
Bit D0 EN_2WIRE

0 = One-wire LVDS output

1 = Two-wire LVDS output



Programmable LVDS Mapping Mode Registers

Register 50h

D15	D14	D13	D12	D11	D10	D9	D8		
ENABLE 50	0	0	0	MAP_Ch1234_to_OUT2A					
D7	D6	D5	D4	D3 D2 D1 D0					
	MAP_Ch123	MAP_Ch123	4_to_OUT1A						

Bit D15 ENABLE 50

This bit enables bits D[11:0] of register 50h.

Bits D[14:12] Must write '0'

Bits D[11:8] MAP_Ch1234_to_OUT2A

These bits set the OUT2A pin pair to the channel data mapping selection.

Bits D[7:4] MAP_Ch1234_to_OUT1B

These bits set the OUT1B pin pair to the channel data mapping selection.

Bits D[3:0] MAP_Ch1234_to_OUT1A

These bits set the OUT1A pin pair to the channel data mapping selection.

Register 51h

D15	D14	D13	D12	D11	D10	D9	D8	
ENABLE 51	0	0	0	MAP_Ch1234_to_OUT3B				
D7	D6	D5	D4	D3 D2 D1 D0				
	MAP_Ch123	4_to_OUT3A		MAP_Ch123	4_to_OUT2B			

Bit D15 ENABLE 51

This bit enables bits D[11:0] of register 51h.

Bits D[14:12] Must write '0'

Bits D[11:8] MAP_Ch1234_to_OUT3B

These bits set the OUT3B pin pair to the channel data mapping selection.

Bits D[7:4] MAP_Ch1234_to_OUT3A

These bits set the OUT3A pin pair to the channel data mapping selection.

Bits D[3:0] MAP_Ch1234_to_OUT2B

These bits set the OUT2B pin pair to the channel data mapping selection.



Register 52h

D15	D14	D13	D12	D11	D10	D9	D8
ENABLE 52	0	0	0	0	0	0	0
D7	D6	D5	D4	D3	D2	D1	D0
	MAP_Ch123	4_to_OUT4B			MAP_Ch123	4_to_OUT4A	

Bit D15 ENABLE 52

This bit enables bits D[7:0] of register 52h.

Bits D[14:8] Must write '0'

Bits D[7:4] MAP_Ch1234_to_OUT4B

These bits set the OUT4B pin pair to the channel data mapping selection.

Bits D[3:0] MAP_Ch1234_to_OUT4A

These bits set the OUT4A pin pair to the channel data mapping selection.

Register 53h

D15	D14	D13	D12	D11	D10	D9	D8		
ENABLE 53	0	0	0		MAP_Ch567	8_to_OUT6B			
D7	D6	D5	D4	D3	D2	D1	D0		
	MAP_Ch567	8_to_OUT5A	MAP_Ch5678_to_OUT5B						

Bit D15 ENABLE 53

This bit enables bits D[11:0] of register 53h.

Bits D[14:12] Must write '0'

Bits D[11:8] MAP_Ch5678_to_OUT6B

These bits set the OUT6B pin pair to the channel data mapping selection.

Bits D[7:4] MAP_Ch5678_to_OUT5A

These bits set the OUT5A pin pair to the channel data mapping selection.

Bits D[3:0] MAP_Ch5678_to_OUT5B

These bits set the OUT5B pin pair to the channel data mapping selection.

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Register 54h

D15	D14	D13	D12	D11	D10	D9	D8	
ENABLE 54	0	0	0		MAP_Ch567	8_to_OUT7A		
D7	D6	D5	D4	D3	D2	D1	D0	
	MAP_Ch5678_to_OUT7B MAP_Ch5678_to_OUT6A							

Bit D15 ENABLE 54

This bit enables bits D[11:0] of register 54h.

Bits D[14:12] Must write '0'

Bits D[11:8] MAP_Ch5678_to_OUT7A

These bits set the OUT7A pin pair to the channel data mapping selection.

Bits D[7:4] MAP_Ch5678_to_OUT7B

These bits set the OUT7B pin pair to the channel data mapping selection.

Bits D[3:0] MAP_Ch5678_to_OUT6A

These bits set the OUT6A pin pair to the channel data mapping selection.

Register 55h

D15	D14	D13	D12	D11	D10	D9	D8
ENABLE 55	0	0	0	0	0	0	0
D7	D6	D5	D4	D3	D2	D1	D0
	MAP_Ch567	8_to_OUT8A			MAP_Ch567	8_to_OUT8B	

Bit D15 ENABLE 55

This bit enables bits D[7:0] of register 55h.

Bits D[14:8] Must write '0'

Bits D[7:4] MAP_Ch5678_to_OUT8A

These bits set the OUT8A pin pair to the channel data mapping selection.

Bits D[3:0] MAP_Ch5678_to_OUT8B

These bits set the OUT8B pin pair to the channel data mapping selection.



Custom Coefficient Registers

Registers 5Ah to 65h⁽¹⁾

D15	D14	D13	D12	D11	D10	D9	D8
EN_CUSTOM_ FILT_CH1	0	0	0		COEFF <i>n</i> _SE	T_CH1[11:0]	
D7	D6	D5	D4	D3	D2	D1	D0
	·		COEFFn_SE	T_CH1[11:0]			

⁽¹⁾ n = 0 to 11.

These registers are the custom coefficient registers for channel 1.

Bit D15 EN_CUSTOM_FILT_CH1

0 = Built-in coefficients are used

1 = Enables custom coefficients to be used

Bits D[14:12] Must write '0'

Bits D[11:0] COEFF*n*_SET_CH1[11:0]

These bits set the custom coefficient *n* for the channel 1 digital filter.

Registers 66h to 71h⁽¹⁾

D15	D14	D13	D12	D11	D10	D9	D8	
EN_CUSTOM_ FILT_CH2	0	0	0		COEFF <i>n</i> _SE	T_CH2[11:0]		
D7	D6	D5	D4	D3	D2	D1	D0	
	COEFFn_SET_CH2[11:0]							

⁽¹⁾ n = 0 to 11.

These registers are the custom coefficient registers for channel 2.

Bit D15 EN_CUSTOM_FILT_CH2

0 = Built-in coefficients are used

1 = Enables custom coefficients to be used

Bits D[14:12] Must write '0'

Bits D[11:0] COEFF*n*_SET_CH2[11:0]

These bits set the custom coefficient *n* for the channel 2 digital filter.



Registers 72h to 7Dh⁽¹⁾

D15	D14	D13	D12	D11	D10	D9	D8	
EN_CUSTOM_ FILT_CH3	0	0	0		COEFF <i>n</i> _SE	T_CH3[11:0]		
D7	D6	D5	D4	D3	D2	D1	D0	
	COEFFn_SET_CH3[11:0]							

⁽¹⁾ n = 0 to 11.

These registers are the custom coefficient registers for channel 3.

Bit D15 EN_CUSTOM_FILT_CH3

0 = Built-in coefficients are used

1 = Enables custom coefficients to be used

Bits D[14:12] Must write '0'

Bits D[11:0] COEFF*n*_SET_CH3[11:0]

These bits set the custom coefficient *n* for the channel 3 digital filter.

Registers 7Eh to 89h⁽¹⁾

D15	D14	D13	D12	D11	D10	D9	D8
EN_CUSTOM_ FILT_CH4	0	0	0		COEFF <i>n</i> _SE	T_CH4[11:0]	
D7	D6	D5	D4	D3	D2	D1	D0
			COEFFn_SE	T_CH4[11:0]			

⁽¹⁾ n = 0 to 11.

These registers are the custom coefficient registers for channel 4.

Bit D15 EN_CUSTOM_FILT_CH4

0 = Built-in coefficients are used

1 = Enables custom coefficients to be used

Bits D[14:12] Must write '0'

Bits D[11:0] COEFF*n*_SET_CH1[11:0]

These bits set the custom coefficient *n* for the channel 4 digital filter.



Registers 8Ah to 95h⁽¹⁾

D15	D14	D13	D12	D11	D10	D9	D8	
EN_CUSTOM_ FILT_CH5	0	0	0		COEFF <i>n</i> _SE	T_CH5[11:0]		
D7	D6	D5	D4	D3	D2	D1	D0	
	COEFFn_SET_CH5[11:0]							

⁽¹⁾ n = 0 to 11.

These registers are the custom coefficient registers for channel 5.

Bit D15 EN_CUSTOM_FILT_CH5

0 = Built-in coefficients are used

1 = Enables custom coefficients to be used

Bits D[14:12] Must write '0'

Bits D[11:0] COEFF*n*_SET_CH5[11:0]

These bits set the custom coefficient *n* for the channel 5 digital filter.

Registers 96h to A1h⁽¹⁾

D15	D14	D13	D12	D11	D10	D9	D8	
EN_CUSTOM_ FILT_CH6	0	0	0		COEFF <i>n</i> _SE	T_CH6[11:0]		
D7	D6	D5	D4	D3	D2	D1	D0	
	COEFFn_SET_CH6[11:0]							

⁽¹⁾ n = 0 to 11.

These registers are the custom coefficient registers for channel 6.

Bit D15 EN_CUSTOM_FILT_CH6

0 = Built-in coefficients are used

1 = Enables custom coefficients to be used

Bits D[14:12] Must write '0'

Bits D[11:0] COEFF*n*_SET_CH6[11:0]

These bits set the custom coefficient *n* for the channel 6 digital filter.



Registers A2h to ADh⁽¹⁾

D15	D14	D13	D12	D11	D10	D9	D8	
EN_CUSTOM_ FILT_CH7	0	0	0		COEFF <i>n</i> _SE	T_CH7[11:0]		
D7	D6	D5	D4	D3	D2	D1	D0	
	COEFFn_SET_CH7[11:0]							

⁽¹⁾ n = 0 to 11.

These registers are the custom coefficient registers for channel 7.

Bit D15 EN_CUSTOM_FILT_CH7

0 = Built-in coefficients are used

1 = Enables custom coefficients to be used

Bits D[14:12] Must write '0'

Bits D[11:0] COEFF*n*_SET_CH7[11:0]

These bits set the custom coefficient *n* for the channel 7 digital filter.

Registers AEh to B9h⁽¹⁾

D15	D14	D13	D12	D11	D10	D9	D8
EN_CUSTOM_ FILT_CH8	0	0	0		COEFF <i>n</i> _SE	T_CH8[11:0]	
D7	D6	D5	D4	D3	D2	D1	D0
			COEFFn_SE	T_CH8[11:0]			

⁽¹⁾ n = 0 to 11.

These registers are the custom coefficient registers for channel 8.

Bit D15 EN_CUSTOM_FILT_CH8

0 = Built-in coefficients are used

1 = Enables custom coefficients to be used

Bits D[14:12] Must write '0'

Bits D[11:0] COEFF*n*_SET_CH8[11:0]

These bits set the custom coefficient *n* for the channel 8 digital filter.



Register BEh

D15	D14	D13	D12	D11	D10	D9	D8
EN_LVDS_ PROG	0	0	0	0	0	DELAY_D	ATA_R[1:0]
D7	D6	D5	D4	D3	D2	D1	D0
DELAY_LCLK_R[2:0]		DELAY_DATA_F[1:0]		DELAY_LCLK_F[2:0]			

Bit D15 This bit enables LVDS edge delay programmability.

Bits D[14:10] Must write '0'

Refer Table 22 for settings. Bits D[9:8] Bits D[7:5] Refer Table 23 for settings. Bits D[4:3] Refer Table 22 for settings. Bits D[2:0] Refer Table 23 for settings.

Register F0h

D15	D14	D13	D12	D11	D10	D9	D8
EN_EXT_REF	0	0	0	0	0	0	0
D7	D6	D5	D4	D3	D2	D1	D0
0	0	0	0	0	0	0	0

The EN_HIGH_ADDRS register bit (register 01h, bit D4) must be set to '1' to allow access to this register.

Bit D15 **EN_EXT_REF**

0 = Internal reference mode (default)

1 = External reference mode enabled; apply the reference voltages on the REFT and REFB

pins

Bits D[14:0] Must write '0'

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APPLICATION INFORMATION

THEORY OF OPERATION

The ADS5295 is a low-power, 8-channel, 12-bit analog-to-digital converter (ADC) with sample rates up to 100 MSPS that run off of a single 1.8-V supply. All eight channels simultaneously sample the analog inputs at the input clock rising edge. The sampled signal is sequentially converted by a series of small resolution stages, with the outputs combined in a digital correction logic block. At every clock edge, the sample propagates through the pipeline, resulting in a data latency of 12 clock cycles.

ANALOG INPUT

The analog input consists of a switched-capacitor-based, differential sample-and-hold architecture, as shown in Figure 46. This differential topology results in very good ac performance even for high input frequencies at high sampling rates. The INP and INM pins must be externally biased around a common-mode voltage of 0.95 V, available on the VCM pin. For a full-scale differential input, each input pin (INP, INN) must swing symmetrically between VCM + 0.5 V and VCM - 0.5 V, resulting in a 2-V_{PP} differential input swing. The input sampling circuit has a high 3-dB bandwidth that extends up to 500 MHz (measured from the input pins to the sampled voltage).

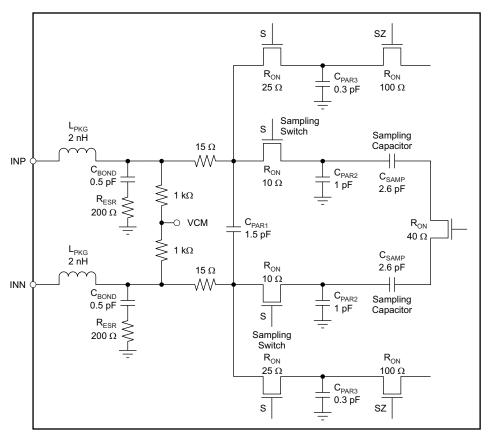
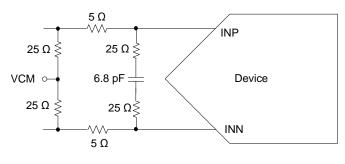


Figure 46. Analog Input Equivalent Circuit



Drive Circuit Requirements

For optimum performance, the analog inputs must be driven differentially. This architecture improves the common-mode noise immunity and even-order harmonic rejection. A small resistor (5 Ω to 10 Ω) in series with each input pin is recommended to damp out ringing caused by package parasitics. The drive circuits in Figure 47 and Figure 48 show an R-C filter across the analog input pins. The purpose of the filter is to absorb the glitches caused by the opening and closing of the sampling capacitors. Figure 49 and Figure 50 show the differential input resistance and capacitance across frequency.



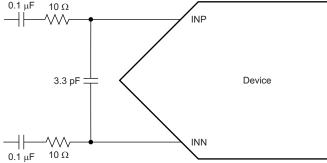
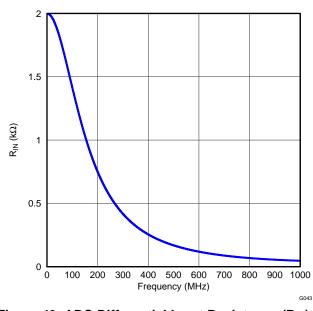


Figure 47. DC-Coupled Drive Circuit with RCR

Figure 48. AC-Coupled Drive Circuit



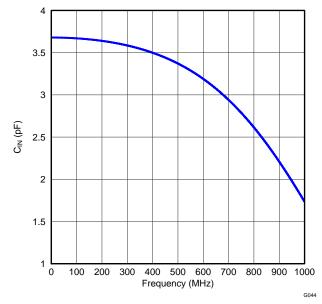


Figure 49. ADC Differential Input Resistance (R_{IN}) vs Frequency

Figure 50. ADC Differential Input Capacitance (CIN) vs Frequency

Large- and Small-Signal Input Bandwidth

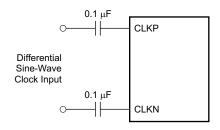
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The small-signal bandwidth of the analog input circuit is high, approximately 500 MHz. When using an amplifier to drive the ADS5295, the total amplifier noise up to the small-signal bandwidth must be considered. The largesignal bandwidth of the device depends on the amplitude of the input signal. The ADS5295 supports a 2-V_{PP} amplitude for input signal frequencies up to 90 MHz. For higher frequencies, the amplitude of the input signal must be decreased proportionally. For example, at 180 MHz, the device supports a maximum 1-V_{PP} signal.



CLOCK INPUT

The ADS5295 can operate with both single-ended (CMOS) and differential input clocks (such as sine wave, LVPECL, and LVDS). Operating with a low-jitter differential clock is recommended for good SNR performance, especially at input frequencies greater than 30 MHz. In the differential mode, the clock inputs are internally biased to a 0.95-V common-mode voltage. While driving with an external LVPECL or LVDS driver, TI recommends ac-coupling the clock signals so that the clock pins are correctly biased to the common-mode voltage (0.95 V). To operate using a single-ended clock, connect a CMOS clock source to CLKP and tie CLKN to GND. The device automatically detects the presence of a single-ended clock without requiring any configuration and disables the internal biasing. Typical clock termination schemes are shown in Figure 51, Figure 52, Figure 53, and Figure 54.



Differential LVPECL Clock Input

R_{TERM}

0.1 μF

CLKP

CLKP

CLKN

Figure 51. Differential Sine-Wave Clock Driving Circuit

0.1 μF

CLKP

Differential
LVDS
Clock Input

0.1 μF

CLKN

Figure 52. Differential LVPECL Clock Driving Circuit

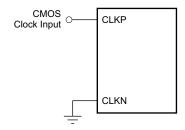


Figure 53. Differential LVDS Clock Driving Circuit

Figure 54. Single-Ended Clock Driving Circuit

EXTERNAL REFERENCE MODE OF OPERATION

For normal operation, the device requires two reference voltages (REFT and REFB) that are generated internally by default, as shown in Figure 55. The value of the reference voltage determines the actual ADC full-scale input voltage, as shown in Equation 1:

Full-Scale Input Voltage = $2 \times (V_{REFT} - V_{REFB})$ (1)

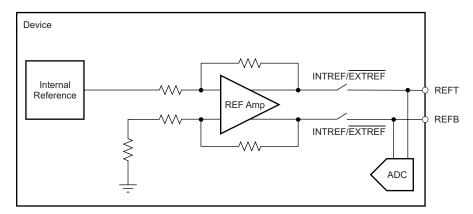


Figure 55. Reference Equivalent Circuit

Any error in the reference results in a deviation of the full-scale input range from its ideal value of 2.0 V_{PP} , as shown in Equation 2:

Error in Full-Scale Voltage =
$$2x [Error in (V_{REFT} - V_{REFB})]$$
 (2)

The reference inaccuracy results in a gain error, which is defined as Equation 3:

$$= 2x \left[\text{Error in } \left(V_{\text{REFT}} - V_{\text{REFB}} \right) \right] \times \frac{100}{2.0}$$
 (3)

To minimize the gain error, the internal reference voltages are trimmed to an accuracy of ±1.5% (or ±30 mV). To obtain even lower gain error, the ADS5295 supports an external reference mode of operation. In this mode, the internal reference amplifiers are powered down and an external amplifier must force the reference voltages on the REFT and REFB pins. For example, this mode can be used to ensure that multiple ADS5295 chips in the system have nearly the same full-scale voltage.

To enable the external reference mode, set the register bits as shown in Table 8. These settings power down the internal reference amplifier and the two reference voltages can be forced directly on the REFT and REFB pins as $V_{REFT} = 1.45 \text{ V}$ and $V_{REFB} = 0.45 \text{ V}$.

Table 8. External Reference Function

FUNCTION	EN_HIGH_ADDRS	EN_EXT_REF	
External reference using the REFT, REFB pins	1	1	

Because the internal reference amplifiers are powered down, the accuracy of the full-scale voltage is determined by the accuracy of $(V_{REFT} - V_{REFB})$, where V_{REFT} is the voltage forced on REFT and V_{REFB} is the voltage forced on REFB.

Note that although the nominal value of $(V_{RFET} - V_{RFEB}) = 1.0 \text{ V}$, ensure that:

$$[(V_{REFT} + V_{REFB}) / 2 = 0.950 \text{ V} \pm 50 \text{ mV}].$$

Figure 56 shows an example of driving the reference pins. The 1-µF bypass capacitor helps provide the switching current drawn by the REFT and REFB pins. The external amplifier must provide an average current of 5 mA or less at 100 MSPS. The performance in the external reference mode depends on the sampling speed. At low sampling speeds (20 MSPS), the performance is the same as that of an internal reference. At higher speeds, the performance degrades because of the effect of the parasitic bond-wire inductance of the REF pins. Figure 57 highlights the difference in SNR between the external and internal reference modes.

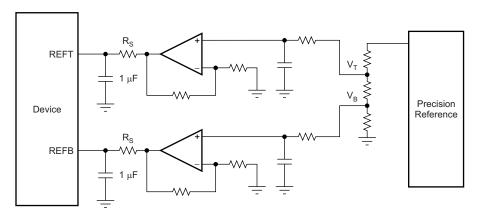


Figure 56. Driving Reference Inputs in External Reference Mode

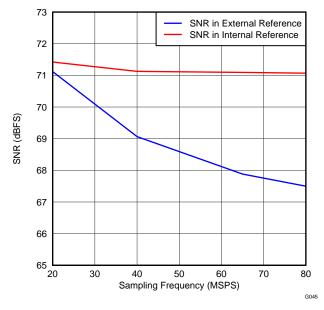
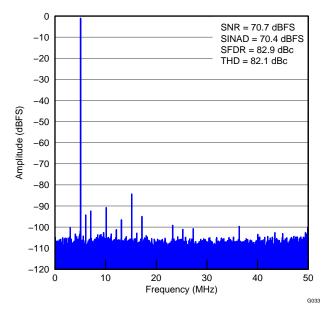


Figure 57. SNR in Internal and External Reference Mode

LOW-FREQUENCY NOISE SUPPRESSION

The low-frequency noise suppression (LFNS) mode is particularly useful in applications where good noise performance is desired in the low-frequency band of dc to 1 MHz. By setting this mode, the low-frequency noise spectrum band around dc is shifted to a similar band around $f_{\rm S}$ / 2 (or the Nyquist frequency). As a result, the noise spectrum from dc to approximately 1 MHz improves significantly, as shown in Figure 58, Figure 59, and Figure 60.

This function can be selectively enabled in each channel using the LFNS_CH register bits. Figure 58, Figure 59, and Figure 60 show the effect of this mode on the spectrum.



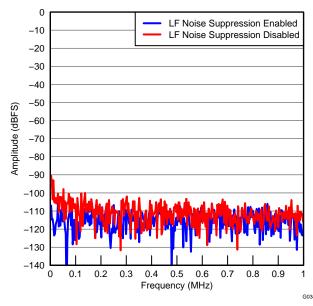


Figure 58. Full-Scale Input Amplitude

Figure 59. Spectrum (Zoomed) From DC to 1 MHz

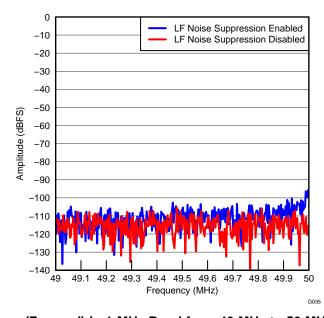


Figure 60. Spectrum (Zoomed) in 1-MHz Band from 49 MHz to 50 MHz ($f_S = 100$ MSPS)



DIGITAL PROCESSING BLOCKS

The ADS5295 integrates a set of commonly-used digital functions that can be used to ease system design. These functions are shown in Figure 61 and are described in the following sections.

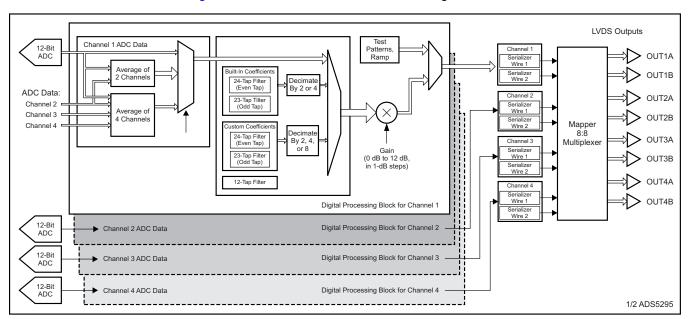


Figure 61. Digital Processing Block Diagram

Digital Gain

The ADS5295 includes programmable digital gain settings from 0 dB to 12 dB in 1-dB steps. The benefit of digital gain is obtaining improved SFDR performance. However, SFDR improvement is achieved at the expense of SNR; for each gain setting, SNR degrades by approximately 1 dB. Therefore, the gain can be used to trade-off between SFDR and SNR.

For each gain setting, the supported analog input full-scale range scales proportionally, as shown in Table 9. After reset, the device comes up in 0-dB gain mode. To use other gain settings, program the GAIN_CH[3:0] register bits.

GAIN_CH[3:0]	DIGITAL GAIN (dB)	ANALOG FULL-SCALE INPUT (VPP)
0000	0	2
0001	1	1.78
0010	2	1.59
0011	3	1.42
0100	4	1.26
0101	5	1.12
0110	6	1
0111	7	0.89
1000	8	0.8
1001	9	0.71
1010	10	0.63
1011	11	0.56
1100	12	0.5
Other combinations	Do not use	_

Product Folder Links: ADS5295

Table 9. Analog Full-Scale Range Across Gains



Digital Filter

The digital processing block includes the option to filter and decimate the ADC data outputs digitally. Various filters and decimation rates are supported: decimation rates of 2, 4, and 8, and low-pass, high-pass, and bandpass filters are available.

The filters are internally implemented as 24-tap symmetric finite impulse response (FIR) filters (even-tap) using the predefined coefficients of Equation 4:

$$y(n) =$$

$$\left[\frac{1}{2^{11}}\right] \times \left[h0.x(n) + h1.x(n-1) + h2.x(n-2) + ... + h11.x(n-11) + h12.x(n-12) + ... + h1.x(n-22) + h0.x(n-23)\right]$$

Alternatively, some filters can be configured as 23-tap symmetric FIR filters (odd-tap), as described in Equation 5:

$$y(n) =$$

$$\left[\frac{1}{2^{11}}\right] \times \left[h0.x(n) + h1.x(n-1) + h2.x(n-2) + ... + h10.x(n-10) + h11.x(n-11) + h10.x(n-12) + ... + h1.x(n-21) + h0.x(n-22)\right]$$
(5)

In Equation 4 and Equation 5, h0 through h11 are 12-bit, signed, twos complement representations of the coefficients (-2048 to +2047). x(n) is the filter input data sequence and y(n) is the filter output sequence.



Details of the registers used for configuring the digital filters are described in the digital filter registers (registers 29h, 2Fh, 30h, 31h, and 38h) and Table 10. Table 10 gives a summary of the register bits to be used for each filter type.

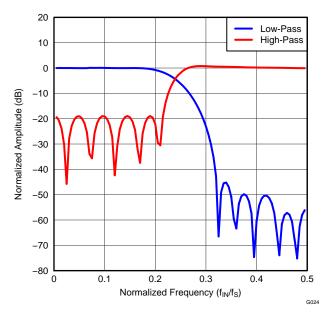
Table 10. Digital Filters

DECIMATION	TYPE OF FILTER	DATA_ RATE	DEC_RATE _CHn ⁽¹⁾	FILTER_ TYPE_CHn	ODD_ TAP_CH <i>n</i>	USE_ FILTER_ CHn	EN_ CUSTOM_ FILT_CH <i>n</i>	EN_DIG_ FILTER
Built-in, low-pass, odd-tap filter (pass band = 0 to f _S / 4)		01	000	000	1	1	0	1
Decimate-by-2	Built-in, high-pass, odd-tap filter (pass band = 0 to f _S / 4)	01	000	001	1	1	0	1
	Built-in, low-pass, even-tap filter (pass band = 0 to $f_S / 8$)	10	001	010	0	1	0	1
Decimate-by-4	Built-in, first band pass, even-tap filter (pass band = $f_S / 8$ to $f_S / 4$)	10	001	011	0	1	0	1
	Built-in, second band pass, even-tap filter (pass band = $f_S / 4$ to 3 $f_S / 8$)	10	001	100	0	1	0	1
	Built-in, high-pass, odd-tap filter (pass band = $3 f_S / 8 \text{ to } f_S / 2$)	10	001	101	1	1	0	1
Decimate-by-2	Custom filter (user-programmable coefficients)	01	000	000	0 or 1	1	1	1
Decimate-by-4	Custom filter (user-programmable coefficients)	10	001	000	0 or 1	1	1	1
Decimate-by-8	Custom filter (user-programmable coefficients)	11	100	000	0 or 1	1	1	1
12-tap filter without decimation	Custom filter (user-programmable coefficients)	00	011	000	0	1	1	1

⁽¹⁾ The DEC_RATE_CH*n* value must be the same for all channels.

Predefined Coefficients

The built-in filter types (low pass, high pass, and band pass) use predefined coefficients. The frequency response of the built-in filters is shown in Figure 62 and Figure 63.



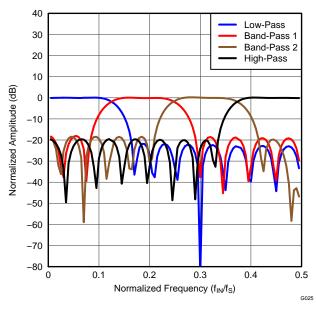


Figure 62. Filter Response (Decimate-by-2)

Figure 63. Filter Response (Decimate-by-4)

The predefined coefficients for the decimate-by-2 and decimate-by-4 filters are listed in Table 11 and Table 12, respectively.

Table 11. Predefined Coefficients for Decimate-by-2 Filters

OCCUPATO	DECIMATE-BY-2						
COEFFICIENTS	LOW-PASS FILTER	HIGH-PASS FILTER					
h0	3	-22					
h1	0	-65					
h2	5	-52					
h3	1	30					
h4	-27	66					
h5	-2	-35					
h6	73	-107					
h7	3	38					
h8	-178	202					
h9	-4	-41					
h10	636	-644					
h11	1024	1061					

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Table 12. Predefined Coefficients for Decimate-by-4 Filters

COEFFICIENTS	DECIMATE-BY-4								
COEFFICIENTS	LOW-PASS FILTER	1st BAND-PASS FILTER	2nd BAND-PASS FILTER	HIGH-PASS FILTER					
h0	-17	-7	-34	40					
h1	– 50	19	-34	-15					
h2	71	-47	-101	- 95					
h3	46	127	43	22					
h4	24	73	58	-8					
h5	-42	0	-28	-81					
h6	-100	86	- 5	106					
h7	- 97	117	-179	-62					
h8	8	-190	294	-97					
h9	202	-464	86	310					
h10	414	-113	-563	-501					
h11	554	526	352	575					

Custom Filter Coefficients

In addition to the built-in filters described in the *Predefined Coefficients* section, customers also have the option of using their own custom, 12-bit, signed coefficients. Because of the symmetric FIR implementation of the filters, only 12 coefficients can be specified with the configuration of Equation 4 or Equation 5. These coefficients (h0 to h11) must be configured in the custom coefficient registers as shown in Equation 6:

The 12 custom coefficients must be loaded into 12 separate registers for each channel (refer to the custom coefficient registers, 5Ah to B9h). The MSB bit of each coefficient register determines whether the built-in filters or custom filters are used. If the EN_CUSTOM_FILT MSB bit is reset to '0', then the built-in filter coefficients are used. Otherwise, the custom coefficients are used.

Custom Filter without Decimation

Another mode is available that enables the use of the digital filter without decimation. In this mode, the filter behaves similar to a 12-tap symmetric FIR filter, as shown in Equation 7: y(n) =

$$\left[\frac{1}{2^{11}}\right] \times \left[h6.x(n) + h7.x(n-1) + h8.x(n-2) + h9.x(n-3) + h10.x(n-4) + h11.x(n-5) + h11.x(n-6) + h10.x(n-7) + h9.x(n-8) + h8.x(n-9) + h7.x(n-10) + h6.x(n-11)\right]$$
(7)

In Equation 7, h6 through h11 are 12-bit, signed, twos complement representations of the coefficients (–2048 to +2047). x(n) is the filter input data sequence and y(n) is the filter output sequence.

In this mode, because the filter is implemented as a 12-tap symmetric FIR, only six custom coefficients must be specified and loaded in registers h6 to h11 (refer to the custom coefficient registers, 5Ah to B9h). To enable this mode, use the register setting specified in bit 15 of registers AEh to B9h.

Digital High-Pass Filter

In addition to the 12 tap filters described previously, the digital processing block also includes a separate high-pass filter for each channel. The high-pass corner frequency can be programmed using bits D[14:10] in register 2Eh.



Digital Averaging

The ADS5295 includes an averaging function where the ADC digital data from two (or four) channels can be averaged. The averaged data are output on specific LVDS channels. Table 13 shows the combinations of the input channels that can be averaged and the LVDS channels on which the averaged data are available.

Table 13. Using Channel Averaging

AVERAGED CHANNELS	OUTPUT WHERE AVERAGED DATA ARE AVAILABLE AT	REGISTER SETTINGS
1, 2	OUT1A, OUT1B	Set AVG_OUT1 = 10 and EN_CHANNEL_AVG = 1
1, 2	OUT3A, OUT3B	Set AVG_OUT3 = 11 and EN_CHANNEL_AVG = 1
3, 4	OUT4A, OUT4B	Set AVG_OUT4 = 10 and EN_CHANNEL_AVG = 1
3, 4	OUT2A, OUT2B	Set AVG_OUT2 = 11 and EN_CHANNEL_AVG = 1
1, 2, 3, 4	OUT1A, OUT1B	Set AVG_OUT1 = 11 and EN_CHANNEL_AVG = 1
1, 2, 3, 4	OUT4A, OUT4B	Set AVG_OUT4 = 11 and EN_CHANNEL_AVG = 1
5, 6	OUT5A, OUT5B	Set AVG_OUT5 = 10 and EN_CHANNEL_AVG = 1
5, 6	OUT7A, OUT7B	Set AVG_OUT7 = 11 and EN_CHANNEL_AVG = 1
7, 8	OUT8A, OUT8B	Set AVG_OUT8 = 10 and EN_CHANNEL_AVG = 1
7, 8	OUT6A, OUT6B	Set AVG_OUT6 = 11 and EN_CHANNEL_AVG = 1
5, 6, 7, 8	OUT5A, OUT5B	Set AVG_OUT5 = 11 and EN_CHANNEL_AVG = 1
5, 6, 7, 8	OUT8A, OUT8B	Set AVG_OUT8 = 11 and EN_CHANNEL_AVG = 1

Performance with Digital Processing Blocks

In applications where higher SNR performance is desired, digital processing blocks (such as averaging and decimation filters) can be used advantageously to achieve this. Table 14 shows the improvement in SNR that can be achieved compared to the default value, using these modes.

Table 14. SNR Improvement Using Digital Processing

MODE ⁽¹⁾	TYPICAL SNR (dB) ⁽²⁾	TYPICAL IMPROVEMENT IN SNR (dB)
Default	70.6	NA
With decimate-by-2 filter enabled	74.64	4.04
With decimate-by-4 filter enabled	76.13	5.53
With decimate-by-8 filter enabled	77.04	6.44
With two channels averaged and decimate-by-4 filter enabled	77.43	6.83
With four channels averaged	76.14	5.54
With four channels averaged and decimate-by-4 filter enabled	79.27	8.67

⁽¹⁾ Custom coefficients are used for the decimate-by-8 filter.

⁽²⁾ In all these modes (except the default one), 14x serialization is used to capture data.



PROGRAMMABLE MAPPING BETWEEN INPUT CHANNELS AND OUTPUT PINS

The ADS5295 has 16 pairs of LVDS channel outputs. The mapping of ADC channels to LVDS output channels is programmable to allow for flexibility in board layout. The control register mapping is shown in Table 15. The 16 LVDS channel outputs are split into two groups of eight LVDS pairs. Within each group, four ADC input channels can be multiplexed to the eight LVDS pairs, depending on the mode of operation (one-wire mode or two-wire mode).

Table 15. Mapping Control Registers

ADDRESS (Hex)	D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0	NAME
	1												Х	Х	Х	Х	MAP_CH1234_TO_OUT1A
50	1								Х	Х	Х	Х					MAP_CH1234_TO_OUT1B
	1				Х	Х	Х	Х									MAP_CH1234_TO_OUT2A
	1												Х	Х	Х	Х	MAP_CH1234_TO_OUT2B
51	1								Х	Х	Х	Х					MAP_CH1234_TO_OUT3A
	1				Х	Х	Х	Х									MAP_CH1234_TO_OUT3B
52	1												Х	Х	Х	Х	MAP_CH1234_TO_OUT4A
52	1								Х	Х	Х	Х					MAP_CH1234_TO_OUT4B
	1												Х	Х	Х	Х	MAP_CH5678_TO_OUT5B
53	1								Х	Х	Х	Х					MAP_CH5678_TO_OUT5A
	1				Х	Х	Х	Х									MAP_CH5678_TO_OUT6B
	1												Х	Х	Х	Х	MAP_CH5678_TO_OUT6A
54	1								Х	Х	Х	Х					MAP_CH5678_TO_OUT7B
	1				Х	Х	Х	Х									MAP_CH5678_TO_OUT7A
EE	1												Х	Х	Х	Х	MAP_CH5678_TO_OUT8B
55	1								Х	Х	Х	Х					MAP_CH5678_TO_OUT8A

Input channels 1 to 4 can be mapped to any LVDS output (OUT1A, OUT1B to OUT4A, OUT4B) using the MAP_CH1234_TO_OUTnA, MAP_CH1234_TO_OUTnB bits, as shown in Table 16.

Table 16. Multiplexing IN1 to IN4

MAP_CH1234_TO_OUTN[3:0] ⁽¹⁾	MAPPING	USED IN ONE-WIRE MODE?	USED IN TWO-WIRE MODE?
0000	ADC input channel IN1 to OUTn	Y	Y (LSB byte)
0001	ADC input channel IN1 to OUT <i>n</i> (two-wire only)	N	Y (MSB byte)
0010	ADC input channel IN2 to OUTn	Y	Y (LSB byte)
0011	ADC input channel IN2 to OUT <i>n</i> (two-wire only)	N	Y (MSB byte)
0100	ADC input channel IN3 to OUTn	Y	Y (LSB byte)
0101	ADC input channel IN3 to OUT <i>n</i> (two-wire only)	N	Y (MSB byte)
0110	ADC input channel IN4 to OUTn	Y	Y (LSB byte)
0111	ADC input channel IN4 to OUT <i>n</i> (two-wire only)	N	Y (MSB byte)
1xxx	LVDS output buffer OUTn powered down	_	_

 $^{(1) \}quad n = 1 \text{A}, \ 1 \text{B}, \ 2 \text{A}, \ 2 \text{B}, \ 3 \text{A}, \ 3 \text{B}, \ 4 \text{A}, \ \text{or} \ 4 \text{B}.$

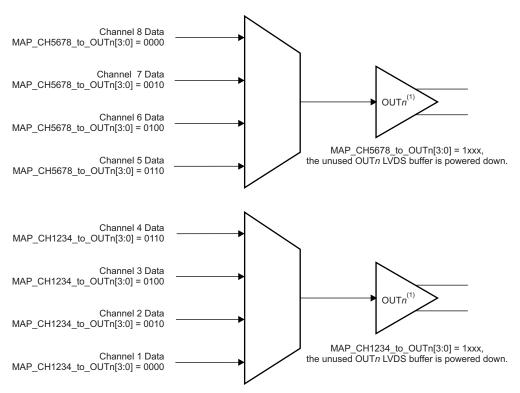


Similarly, input channels 5 to 8 can be mapped to any LVDS output (OUT5A, OUT5B to OUT8A, OUT8B) using the MAP_CH5678_TO_OUTnA, MAP_CH5678_TO_OUTnB bits, as shown in Table 17. Both multiplexing options are controlled by registers 50h to 55h. Channel mapping block diagrams for one-wire mode and two-wire mode are illustrated in Figure 64 and Figure 65, respectively.

Table 17. Multiplexing IN5 to IN8

MAP_CH5678_TO_OUTN[3:0] ⁽¹⁾	MAPPING	USED IN ONE-WIRE MODE?	USED IN TWO-WIRE MODE?
0000	ADC input channel IN8 to OUTn	Y	Y (LSB byte)
0001	ADC input channel IN8 to OUT <i>n</i> (two-wire only)	N	Y (MSB byte)
0010	ADC input channel IN7 to OUTn	Y	Y (LSB byte)
0011	ADC input channel IN7 to OUT <i>n</i> (two-wire only)	N	Y (MSB byte)
0100	ADC input channel IN6 to OUTn	Υ	Y (LSB byte)
0101	ADC input channel IN6 to OUT <i>n</i> (two-wire only)	N	Y (MSB byte)
0110	ADC input channel IN5 to OUTn	Y	Y (LSB byte)
0111	ADC input channel IN5 to OUT <i>n</i> (two-wire only)	N	Y (MSB byte)
1xxx	LVDS output buffer OUT <i>n</i> powered down	_	_

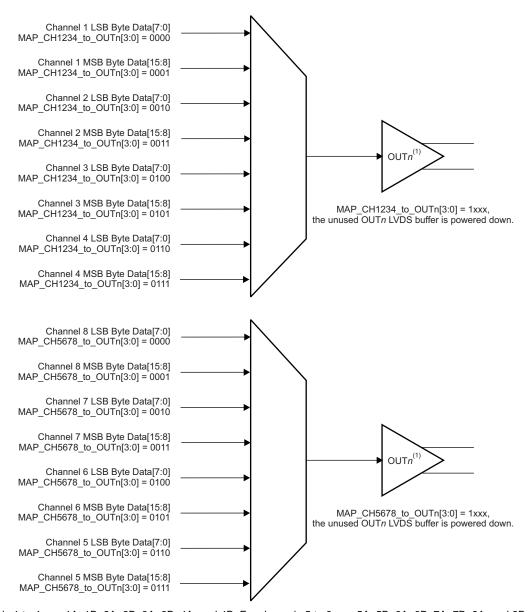
(1) n = 5A, 5B, 6A, 6B, 7A, 7B, 8A, or 8B.



 $(1) \ \ \text{For channels 1 to 4, n = 1A, 1B, 2A, 2B, 3A, 3B, 4A, and 4B. For channels 5 to 8, n = 5A, 5B, 6A, 6B, 7A, 7B, 8A, and 8B.}$

Figure 64. One-Wire Channel Mapping Mode





 $(1) \ \ \text{For channels 1 to 4, n = 1A, 1B, 2A, 2B, 3A, 3B, 4A, and 4B. For channels 5 to 8, n = 5A, 5B, 6A, 6B, 7A, 7B, 8A, and 8B.}$

Figure 65. Two-Wire Channel Mapping Mode



The default mapping for the one-wire and two-wire modes is shown in Table 18 and Table 19, respectfully.

Table 18. Mapping for One-Wire Mode

ANALOG INPUT CHANNEL	LVDS OUTPUT ⁽¹⁾
Channel IN1	OUT1A
Channel IN2	OUT2A
Channel IN3	OUT3A
Channel IN4	OUT4A
Channel IN5	OUT5A
Channel IN6	OUT6A
Channel IN7	OUT7A
Channel IN8	OUT8A

⁽¹⁾ ADC data are only available on OUTnA with default register settings.

Table 19. Mapping for Two-Wire Mode

ANALOG INPUT CHANNEL	LVDS OUTPUT ⁽¹⁾
Channel IN1	OUT1A, OUT1B
Channel IN2	OUT2A, OUT2B
Channel IN3	OUT3A, OUT3B
Channel IN4	OUT4A, OUT4B
Channel IN5	OUT5A, OUT5B
Channel IN6	OUT6A, OUT6B
Channel IN7	OUT7A, OUT7B
Channel IN8	OUT8A, OUT8B

⁽¹⁾ ADC data are available on both OUTnA and OUTnB.



SYNCHRONIZATION USING THE SYNC PIN

The SYNC pin can be used to synchronize the data output from channels within the same chip or from channels across multiple chips when decimation filters are used with a reduced output data rate. When decimation filters are used (if the decimate-by-2 filter is enabled, for example), then effectively, the device outputs one digital code for every two analog input samples. If the SYNC pulse is not used, then the filters are not synchronized (even within a chip). When the filters are not synchronized, one channel may be transmitting codes corresponding to input samples N, N+1, and so on, while another channel may be transmitting codes corresponding to N+1, N+2, and so on.

To achieve synchronization across multiple chips, the SYNC pulse must arrive at all ADS5295 chips at the same time (as shown in Figure 66). The ADS5295 generates an internal synchronization signal that resets the internal clock dividers used by the decimation filter. Using the SYNC signal in this way ensures that all channels output digital codes corresponding to the same set of input samples.

Synchronizing the filters using the SYNC pin is enabled by default. No register bits are required to be written. The TP_HARD_SYNC register bit must be reset to '0' for this mode to function properly. As shown in Figure 66, the SYNC rising edge can be positioned anywhere within the window. SYNC width must be at least one clock cycle.

In addition, SYNC can also be used to synchronize the RAMP test patterns across channels. In order to synchronize the test patterns, TP_HARD_SYNC must be set to '1'. Setting TP_HARD_SYNC to '1' actually disables the sync of the filters.

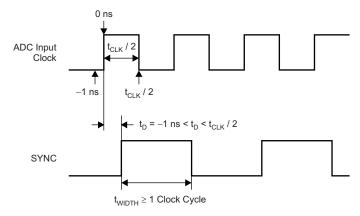


Figure 66. SYNC Timing Diagram

Synchronizing ADC Sampling Instants

Note that SYNC does not and cannot be used to synchronize the ADC sampling instants across chips. All channels within a single chip sample the analog inputs simultaneously. To ensure that channels across two chips sample the analog inputs simultaneously, the input clock must be routed to both chips with an identical length. This layout ensures that the input clocks arrive at both chips at the same time. Therefore, the SYNC pin cannot be used to synchronize the sampling instants because the input clock routing must be implemented during board design.

DIGITAL OUTPUT INTERFACE

SERIAL LVDS INTERFACE

The ADS5295 offers several flexible output options, making the device easy to interface to an application-specific integrated circuit (ASIC) or a field-programmable gate array (FPGA). Each option can be easily programmed using the serial interface. A summary of all available options is listed in Table 20 along with the default values after power-up and reset. Following Table 20, each option is described in detail. Table 21 lists the two-wire register settings for the LVDS interface.

Table 20. Summary of Output Interface Options

		AVAILA	ABLE IN:	DEFAULT AFTER	
FEATURE	OPTIONS	ONE- WIRE	TWO- WIRE	POWER-UP AND RESET	BRIEF DESCRIPTION
Wire interface	One- and two-wire	N	N	One-wire	One-wire: ADC data are sent serially over one pair of LVDS pins. Two-wire: ADC data are split and sent serially over two pairs of LVDS pins.
	12x	Υ	Υ	12x	
	10x	Y	Υ	12x	
Serialization factor	14x	Υ	Υ		To be used with digital processing functions, such as averaging and decimation filers.
	16x	Υ	N		To be used with digital processing functions, such as averaging and decimation filers.
	6x, 5x, 7x, 8x	Υ	N	6x	Only available with one-wire interface for 12x, 10x, 14x, and 16x serialization factors, respectively.
DDR bit clock frequency	3x, 2.5x, 3.5x, 4x	N	Y	6x	Only available with two-wire interface for 12x, 10x, 14x, and 16x serialization factors, respectively.
	1x sample rate	Υ	N	1x	
Frame clock frequency	1/2x sample rate	N	Υ	1x	
	Byte-wise	N	Υ	Byte-wise	Only available with the two-wire interface. Byte-wise: the ADC data are split into upper and lower bytes that are output on separate wires.
Bit sequence	Bit-wise	N	Y	Byte-wise	Only available with the two-wire interface. Bit-wise: the ADC data are split into even and odd bits that are output on separate wires.
	Word-wise	N	Y	Byte-wise	Only available with the two-wire interface. Word-wise: successive ADC data samples are sent over separate wires.

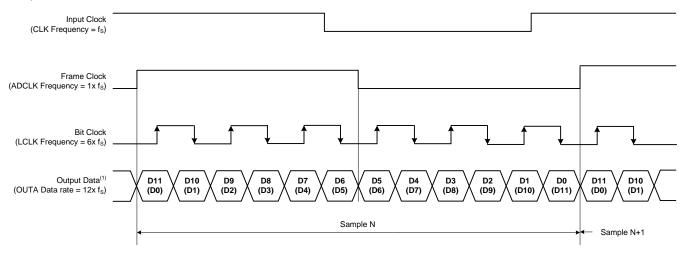
Table 21. Register Settings for Two-wire LVDS Interface

D15 (EN_WORD_BIT_WISE)	D8 (EN_BIT_WISE)	LVDS OUTPUT	
0	X	X	Byte-wise mode
1	X	1	Word-wise mode
1	1	0	Bit-wise mode



One-Wire, 12x Serialization with DDR Bit Clock and 1x Frame Clock

The 12-bit ADC data are serialized and output over one LVDS pair per channel along with a 6x bit clock and a 1x frame clock, as shown in Figure 67. The output data rate is a 12x sample rate; therefore, it is suited for low sample rates.

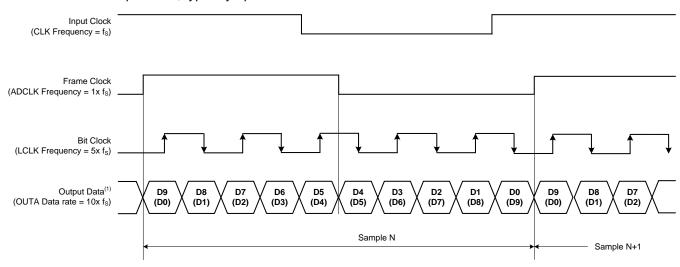


(1) The upper data bit is the MSB-first mode data bit and the lower data bit is the LSB-first mode data bit.

Figure 67. LVDS Output Interface Timing Diagram (One-Wire, 12x Serialization)

One-Wire, 10x Serialization with DDR Bit Clock and 1x Frame Clock

The 10 upper bits of the 12-bit ADC data are serialized and output over one LVDS pair per channel along with a 5x bit clock and a 1x frame clock, as shown in Figure 68. The output data rate is a 10x sample rate; therefore, it is suited for low sample rates, typically up to 65 MSPS.



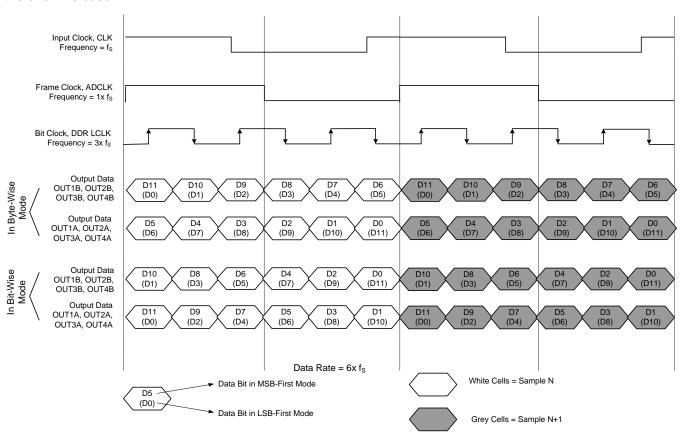
(1) The upper data bit is the MSB-first mode data bit and the lower data bit is the LSB-first mode data bit.

Figure 68. LVDS Output Interface Timing Diagram (One-Wire, 10x Serialization)



Two-Wire, 12x Serialization with DDR Bit Clock and 1/2x Frame Clock

The 12-bit ADC data are serialized and output over two LVDS pairs per channel, as shown in Figure 69 and Figure 70. The output data rate is a 12x sample rate with a 3x bit clock and a 1/2x frame clock. This interface can be used up to the maximum sample rate of the device because the output data rate is half of the data rate in the one-wire case.



- (1) The upper data bit is the MSB-first mode data bit and the lower data bit is the LSB-first mode data bit.
- (2) Shaded cells correspond to N+1 samples. Unshaded cells correspond to N samples.

Figure 69. LVDS Output Interface Timing Diagram (Two-Wire, 12x Serialization, Byte-Wise and Bit-Wise Modes)



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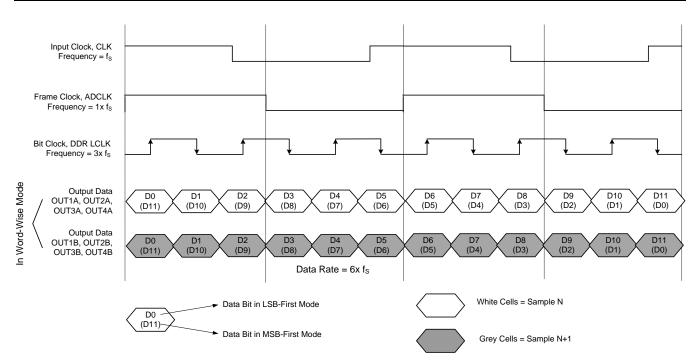
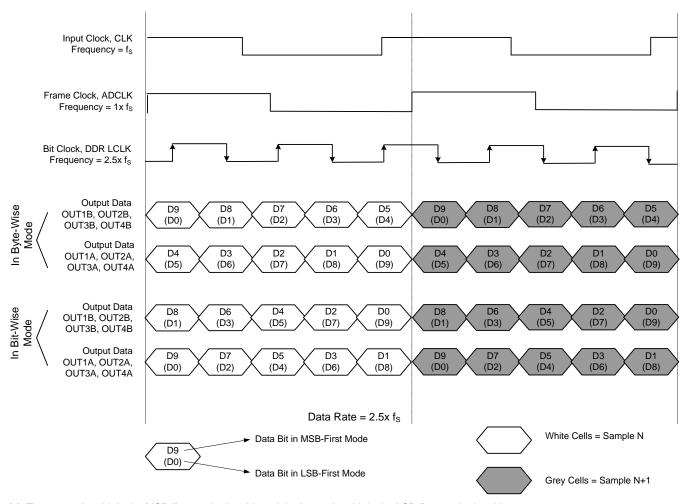


Figure 70. LVDS Output Interface Timing Diagram (Two-Wire, 12x Serialization, Word-Wise Mode)



Two-Wire, 10x Serialization with DDR Bit Clock and 1/2x Frame Clock

The 10 upper bits of the 12-bit ADC data are serialized and output over two LVDS pairs per channel, as shown in Figure 71. The output data rate is a 5x sample rate per wire with a 2.5x bit clock and a 1/2x frame clock. This interface can be used up to the maximum sample rate of the device because the output data rate is half of the data rate in the one-wire case.



- (1) The upper data bit is the MSB-first mode data bit and the lower data bit is the LSB-first mode data bit.
- (2) Shaded cells correspond to N+1 samples. Unshaded cells correspond to N samples.

Figure 71. LVDS Output Interface Timing Diagram (Two-Wire, 10x Serialization)

When digital signal processing functions are used, the 14x and 16x serialization modes can also be used. These modes are:

- One-wire, 14x and 16x serialization with DDR bit clock and 1x frame clock mode, and
- Two-wire, 14x with DDR bit clock and 1/2x frame clock mode.

TEXAS INSTRUMENTS

PROGRAMMABLE LCLK PHASE

The ADS5295 enables the edge of the output bit clock (LCLK) to be programmed with the PHASE_DDR register bits. The default value of PHASE_DDR after reset is '10'. The default phase is shown in Figure 72.

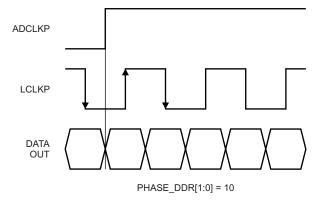


Figure 72. Default LCLK Phase

The phase can also be changed by changing the value of the PHASE_DDR[1:0] bits, as shown in Figure 73.

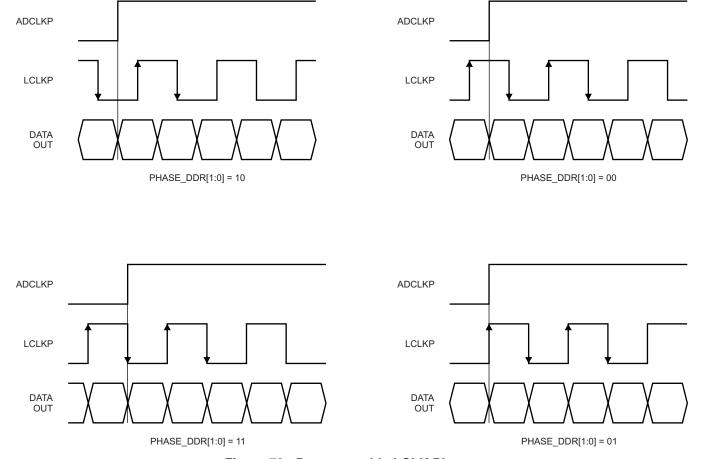
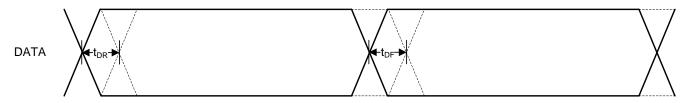


Figure 73. Programmable LCLK Phases

PROGRAMMABLE LVDS OUTPUT CLOCK AND DATA EDGES

The ADS5295 enables the edges of the output data and output bit clock to be programmed with the DELAY_DATA and DELAY_LCLK register bits.

Figure 74 details the timing of the output data and clock edge movements. Table 22 and Table 23 show the register settings and corresponding delay values for the data and clock edge movements.



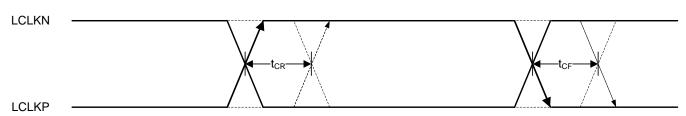


Figure 74. LVDS Interface Output Data and Clock Edge Movement

Table 22. LVDS Interface Output Data Delay Settings⁽¹⁾

DELAY_D/	ATA_R[1:0]	DATA DELAY, RISING CLOCK EDGE t _{DR} , Typical (ps)	DELAY_D	ATA_F[1:0]	DATA DELAY, FALLING CLOCK EDGE t _{DF} , Typical (ps)
0	0	0	0	0	0
0	1	33	0	1	33
1	0	72	1	0	72
1	1	120	1	1	120

⁽¹⁾ Delay settings are the same for both 10x and 12x serialization modes.

Table 23. LVDS Interface Output Clock Delay Settings⁽¹⁾

DELAY_LCLK_R[2:0]			CLOCK RISING EDGE DELAY t _{CR} , Typical (ps)	DELA	Y_LCLK_	F[2:0]	CLOCK FALLING EDGE DELAY t _{CF} , Typical (ps)
0	0	0	0	0	0	0	0
0	0	1	33	0	0	1	33
0	1	0	72	0	1	0	72
0	1	1	120	0	1	1	120
1	0	0	106	1	0	0	106
1	0	1	159	1	0	1	159
1	1	0	202	1	1	0	202
1	1	1	244	1	1	1	244

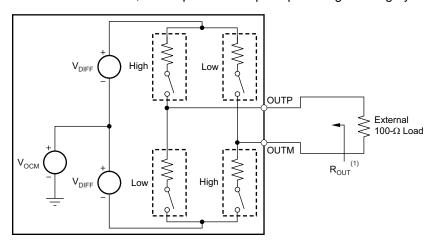
⁽¹⁾ Delay settings are the same for both 10x and 12x serialization modes.



LVDS OUTPUT DATA AND CLOCK BUFFERS

The equivalent circuit of each LVDS output buffer is shown in Figure 75. After reset, the buffer presents an output impedance of 100 Ω to match with the external 100- Ω termination.

The V_{DIFF} voltage is nominally 350 mV, resulting in an output swing of ± 350 mV with a $100-\Omega$ external termination. The buffer output impedance behaves in the same way as a source-side series termination. By absorbing reflections from the receiver end, this impedance helps improve signal integrity.



(1) $R_{OUT} = 100 \Omega$.

Figure 75. LVDS Buffer Equivalent Circuit

OUTPUT DATA FORMAT

Two output data formats are supported: twos complement and offset binary. These formats can be selected by the BTC_MODE serial interface register bit. In the event of an input voltage overdrive, the digital outputs go to the appropriate full-scale level. For a positive overload, the 12-bit output data (D[11:0]) is FFFh in offset binary output format and 7FFh in twos complement output format. For a negative input overload, the output data is 000h in offset binary output format and 800h in twos complement output format.

BOARD DESIGN CONSIDERATIONS

Grounding

A single ground plane is sufficient to give good performance, provided the analog, digital, and clock sections of the board are cleanly partitioned. See the EVM User Guide (*ADS5295*, *8-Channel ADC Evaluation Module*, SLAU442) for details on layout and grounding.

Supply Decoupling

Minimal external decoupling can be used without loss in performance because the ADS5295 already includes internal decoupling. Note that decoupling capacitors can help filter external power-supply noise; thus, the optimum number of capacitors would depend on the actual application. The decoupling capacitors should be placed very close to the converter supply pins.

Exposed Pad

In addition to providing a path for heat dissipation, the pad is also electrically connected to the digital ground internally. Therefore, the exposed pad must be soldered to the ground plane for best thermal and electrical performance.

DEFINITION OF SPECIFICATIONS

Analog Bandwidth: The analog input frequency at which the power of the fundamental is reduced by 3 dB with respect to the low-frequency value.

Aperture Delay: The delay in time between the rising edge of the input sampling clock and the actual time at which the sampling occurs. This delay is different across channels. The maximum variation is specified as aperture delay variation (channel-to-channel).

Aperture Uncertainty (jitter): The sample-to-sample variation in aperture delay.

Clock Pulse Width (duty cycle): The duty cycle of a clock signal is the ratio of the time that the clock signal remains at a logic high (clock pulse width) to the period of the clock signal. Duty cycle is typically expressed as a percentage. A perfect differential sine-wave clock results in a 50% duty cycle.

Maximum Conversion Rate: The maximum sampling rate at which specified operation is given. All parametric testing is performed at this sampling rate, unless otherwise noted.

Minimum Conversion Rate: The minimum sampling rate at which the ADC functions.

Differential Nonlinearity (DNL): An ideal ADC exhibits code transitions at analog input values spaced exactly 1 LSB apart. DNL is the deviation of any single step from this ideal value, measured in units of LSBs.

Integral Nonlinearity (INL): INL is the deviation of the ADC transfer function from a best-fit line determined by a least-squares curve fit of that transfer function, measured in units of LSBs.

Gain Error: Gain error is the deviation of the actual ADC input full-scale range from its ideal value. The gain error is given as a percentage of the ideal input full-scale range. Gain error has two components: error as a result of reference inaccuracy and error as a result of the channel. Both errors are specified independently as E_{GREF} and E_{GCHAN} , respectively. To a first-order approximation, the total gain error is $(E_{TOTAL} \sim E_{GREF} + E_{GCHAN})$. For example, if $E_{TOTAL} = \pm 0.5\%$, then the full-scale input varies from $[(1 - 0.5 / 100) \times FS_{IDEAL}]$ to [(1 + 0.5 / 100)× FS_{IDEAI}].

Offset Error: Offset error is the difference, given in number of LSBs, between the actual average ADC idle channel output code and the ideal average idle channel output code. This quantity is often mapped into millivolts.

Temperature Drift: The temperature drift coefficient (with respect to gain error and offset error) specifies the change per degree Celsius of the parameter from T_{MIN} to T_{MAX}. Drift is calculated by dividing the maximum deviation of the parameter across the T_{MIN} to T_{MAX} range by the difference of $T_{MAX} - T_{MIN}$.

Signal-to-Noise Ratio (SNR): SNR is the ratio of the power of the fundamental (PS) to the noise floor power (P_N), excluding the power at dc and the first nine harmonics. SNR is either given in units of dBc (dB to carrier) when the absolute power of the fundamental is used as the reference, or dBFS (dB to full-scale) when the power of the fundamental is extrapolated to the converter full-scale range.

$$SNR = 10 Log^{10} \frac{P_S}{P_N}$$
 (8)

Signal-to-Noise and Distortion (SINAD): SINAD is the ratio of the power of the fundamental (P_S) to the power of all the other spectral components, including noise (P_N) and distortion (P_D), but excluding dc. SINAD is either given in units of dBc (dB to carrier) when the absolute power of the fundamental is used as the reference, or dBFS (dB to full-scale) when the power of the fundamental is extrapolated to the converter full-scale range.

$$SINAD = 10 Log^{10} \frac{P_S}{P_N + P_D}$$
(9)

Effective Number of Bits (ENOB): ENOB is a measure of the converter performance as compared to the theoretical limit based on quantization noise.

$$ENOB = \frac{SINAD - 1.76}{6.02}$$
(10)

Total Harmonic Distortion (THD): THD is the ratio of the power of the fundamental (Ps) to the power of the first nine harmonics (P_D). THD is typically given in units of dBc (dB to carrier).

THD = 10 Log¹⁰ $\frac{P_s}{P_N}$ (11)

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Spurious-Free Dynamic Range (SFDR): SFDR is the ratio of power of the fundamental to the highest other spectral component (either spur or harmonic). SFDR is typically given in units of dBc (dB to carrier).

Two-Tone Intermodulation Distortion (IMD3): IMD3 is the ratio of the power of the fundamental (at frequencies f_1 and f_2) to the power of the worst spectral component at either frequency $2 f_1 - f_2$ or $2 f_2 - f_1$. IMD3 is either given in units of dBc (dB to carrier) when the absolute power of the fundamental is used as the reference, or dBFS (dB to full-scale) when the power of the fundamental is extrapolated to the converter full-scale range.

AC Power-Supply Rejection Ratio (AC PSRR): AC PSRR is the measure of rejection of variations in the supply voltage by the ADC. If ΔV_{SUP} is the change in supply voltage and ΔV_{OUT} is the resultant change of the ADC output code (referred to the input), then:

PSRR = 20 Log¹⁰
$$\frac{\Delta V_{OUT}}{\Delta V_{SUP}}$$
 (Expressed in dBc) (12)

Voltage Overload Recovery: The number of clock cycles taken to recover to less than 1% error after an overload on the analog inputs. This recovery is tested by separately applying a sine-wave signal with 6-dB positive and negative overload. The deviation of the first few samples after the overload (from the expected values) is noted.

Common-Mode Rejection Ratio (CMRR): CMRR is the measure of rejection of variation in the analog input common-mode by the ADC. If ΔV_{CM_IN} is the change in the common-mode voltage of the input pins and ΔV_{OUT} is the resulting change of the ADC output code (referred to the input), then:

CMRR =
$$20 \log^{10} \frac{\Delta V_{OUT}}{\Delta V_{CM}}$$
 (Expressed in dBc) (13)

CROSSTALK: (only for multichannel ADCs) Crosstalk is a measure of the internal coupling of a signal from an adjacent channel into the channel of interest. Crosstalk is specified separately for coupling from the immediate neighboring channel (near-channel) and for coupling from a channel across the package (far-channel). Crosstalk is usually measured by applying a full-scale signal in the adjacent channel. Crosstalk is the ratio of the power of the coupling signal (as measured at the output of the channel of interest) to the power of the signal applied at the adjacent channel input. Crosstalk is typically expressed in dBc.



PACKAGE OPTION ADDENDUM

24-Jan-2013

PACKAGING INFORMATION

www.ti.com

Orderable Device	Status	Package Type	_		Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Top-Side Markings	Samples
	(1)		Drawing			(2)		(3)		(4)	
ADS5295PFP	ACTIVE	HTQFP	PFP	80	96	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-40 to 85	ADS5295	Samples
ADS5295PFPR	ACTIVE	HTQFP	PFP	80	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-40 to 85	ADS5295	Samples
ADS5295PFPT	ACTIVE	HTQFP	PFP	80	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-40 to 85	ADS5295	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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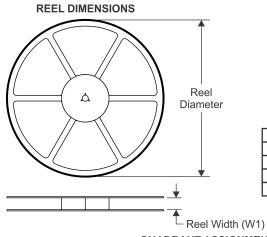
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

⁽⁴⁾ Only one of markings shown within the brackets will appear on the physical device.

PACKAGE MATERIALS INFORMATION

www.ti.com 12-Feb-2013

TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
ADS5295PFPR	HTQFP	PFP	80	1000	330.0	24.4	15.0	15.0	1.5	20.0	24.0	Q2
ADS5295PFPT	HTQFP	PFP	80	250	330.0	24.4	15.0	15.0	1.5	20.0	24.0	Q2

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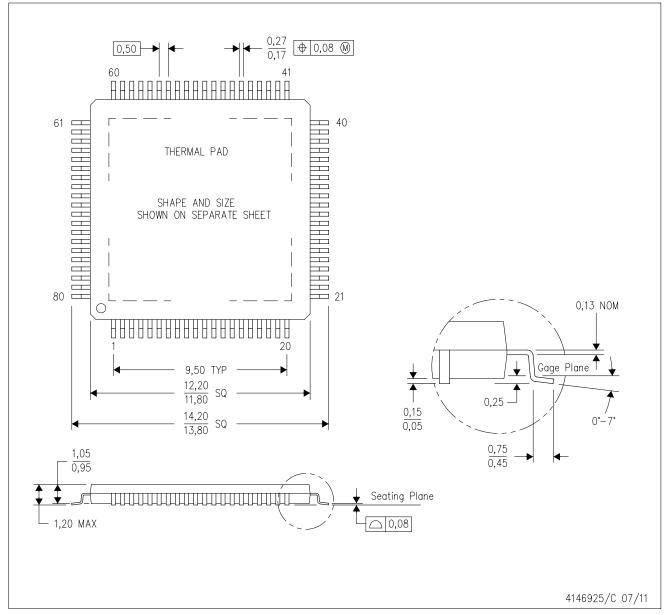


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
ADS5295PFPR	HTQFP	PFP	80	1000	367.0	367.0	45.0
ADS5295PFPT	HTQFP	PFP	80	250	367.0	367.0	45.0

PFP (S-PQFP-G80)

PowerPAD™ PLASTIC QUAD FLATPACK



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion
- D. This package is designed to be soldered to a thermal pad on the board. Refer to Technical Brief, PowerPad Thermally Enhanced Package, Texas Instruments Literature No. SLMA002 for information regarding recommended board layout. This document is available at www.ti.com https://www.ti.com>.
- E. See the additional figure in the Product Data Sheet for details regarding the exposed thermal pad features and dimensions.
- F. Falls within JEDEC MS-026

PowerPAD is a trademark of Texas Instruments.



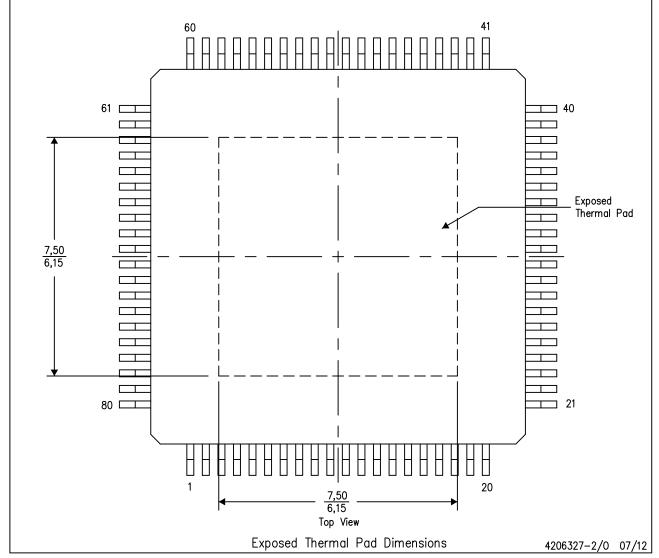
PowerPAD™ PLASTIC QUAD FLATPACK

THERMAL INFORMATION

This PowerPAD package incorporates an exposed thermal pad that is designed to be attached to a printed circuit board (PCB). The thermal pad must be soldered directly to the PCB. After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For additional information on the PowerPAD package and how to take advantage of its heat dissipating abilities, refer to Technical Brief, PowerPAD Thermally Enhanced Package, Texas Instruments Literature No. SLMA002 and Application Brief, PowerPAD Made Easy, Texas Instruments Literature No. SLMA004. Both documents are available at www.ti.com.

The exposed thermal pad dimensions for this package are shown in the following illustration.



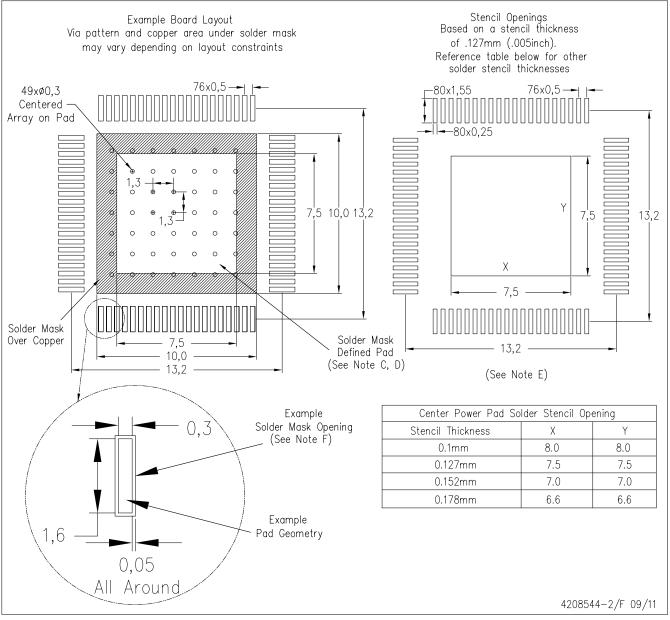
NOTE: A. All linear dimensions are in millimeters

PowerPAD is a trademark of Texas Instruments



PFP (S-PQFP-G80)

PowerPAD™ PLASTIC QUAD FLATPACK



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
- D. This package is designed to be soldered to a thermal pad on the board. Refer to Technical Brief, PowerPad Thermally Enhanced Package, Texas Instruments Literature No. SLMA002, SLMA004, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at www.ti.com http://www.ti.com. Publication IPC-7351 is recommended for alternate designs.
- E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.
- F. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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